

AttAcc! Unleashing the Power of PIM for Batched Transformer-based Generative Model Inference

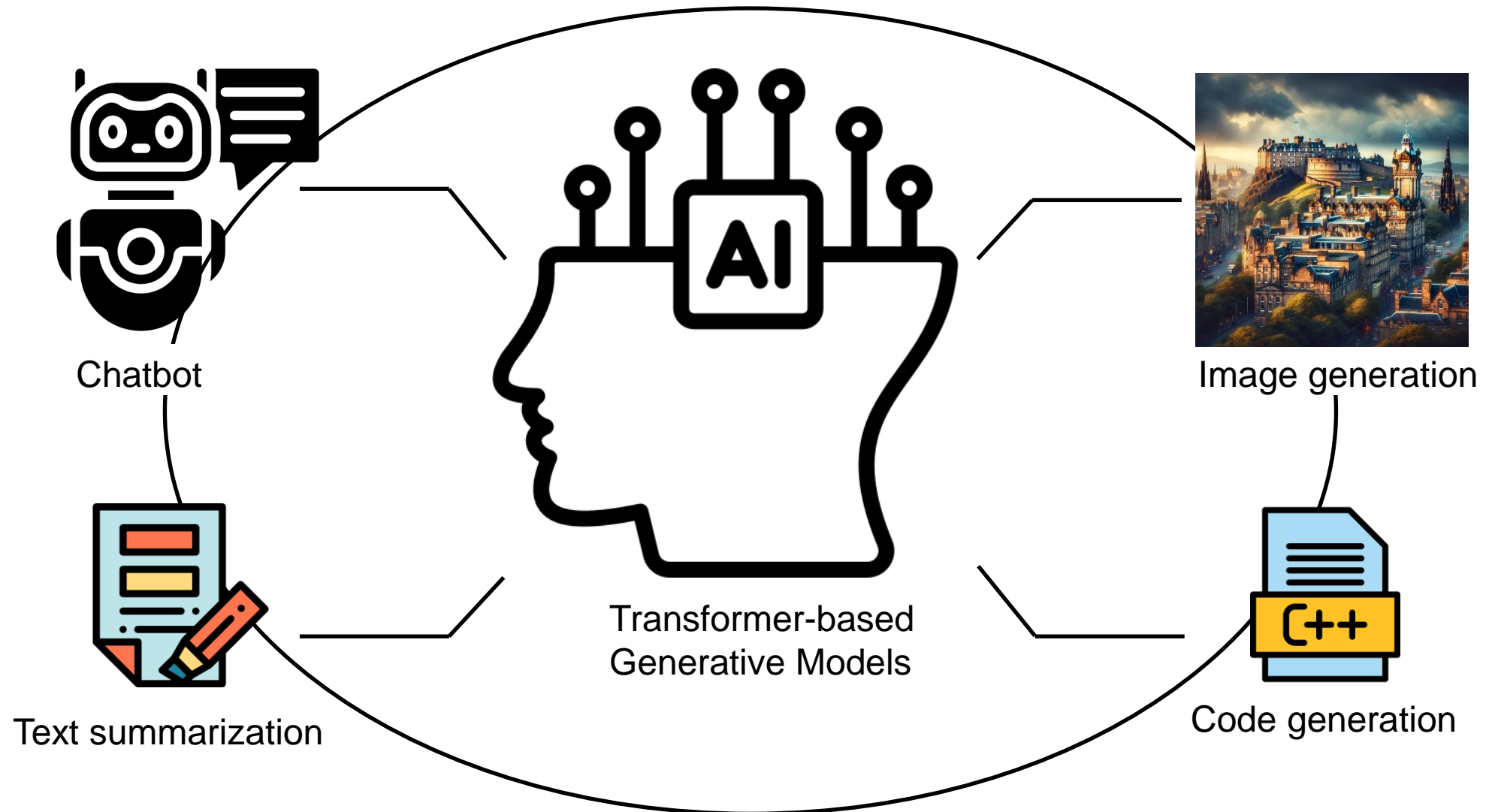
Jaehyun Park^{*†}, Jaewan Choi^{*†}, **Kwanhee Kyung[†]**, Michael Jaemin Kim[†],
Yongsuk Kwon[†], Nam Sung Kim[‡], Jung Ho Ahn[†]

[†] Seoul National University, [‡] University of Illinois Urbana Champaign

^{*} Equally contributed

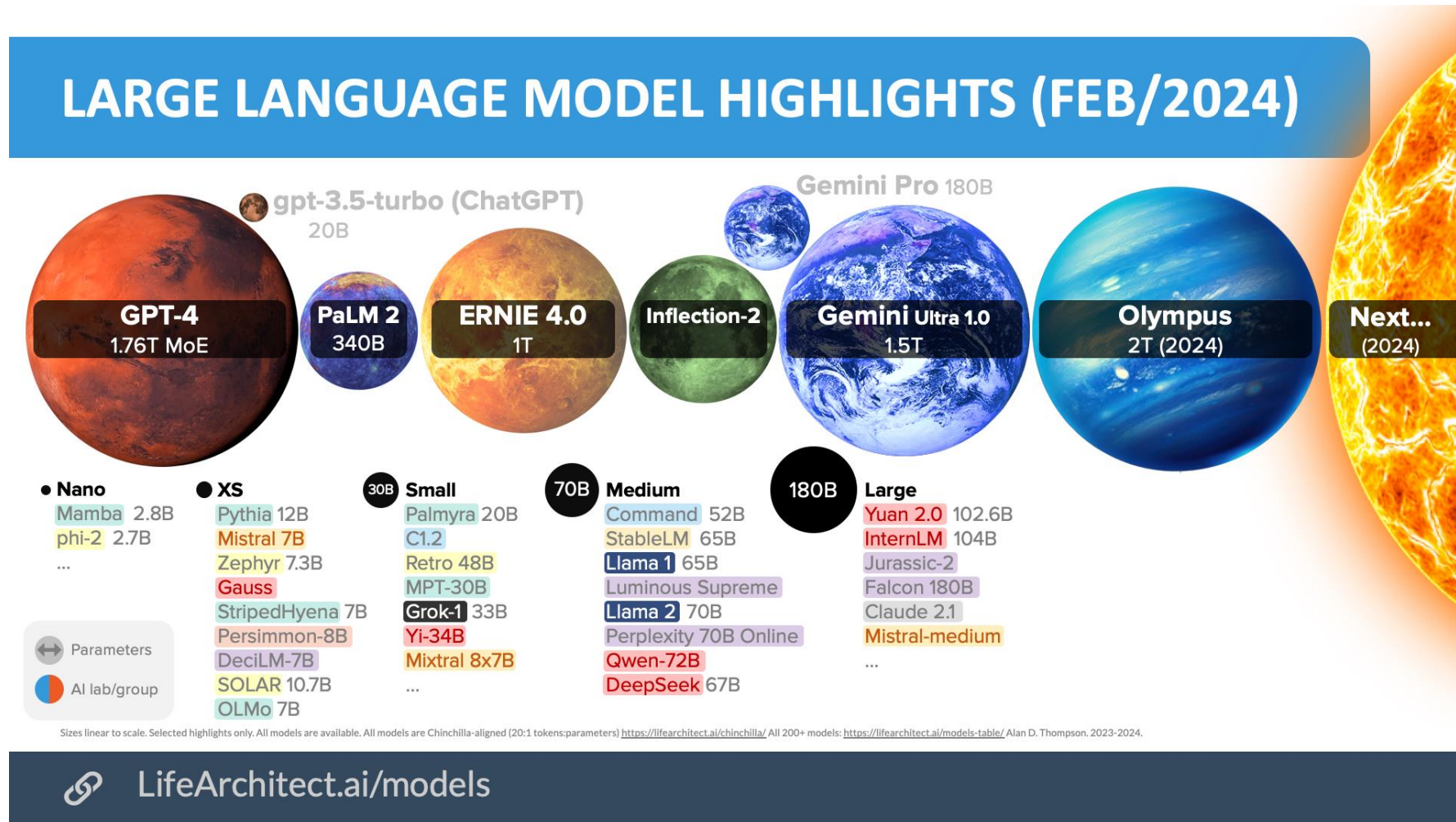
Presenter: Kwanhee Kyung (kwanhee.kyung@scale.snu.ac.kr)

Why Transformer-based Generative Model (TbGM) Inference?



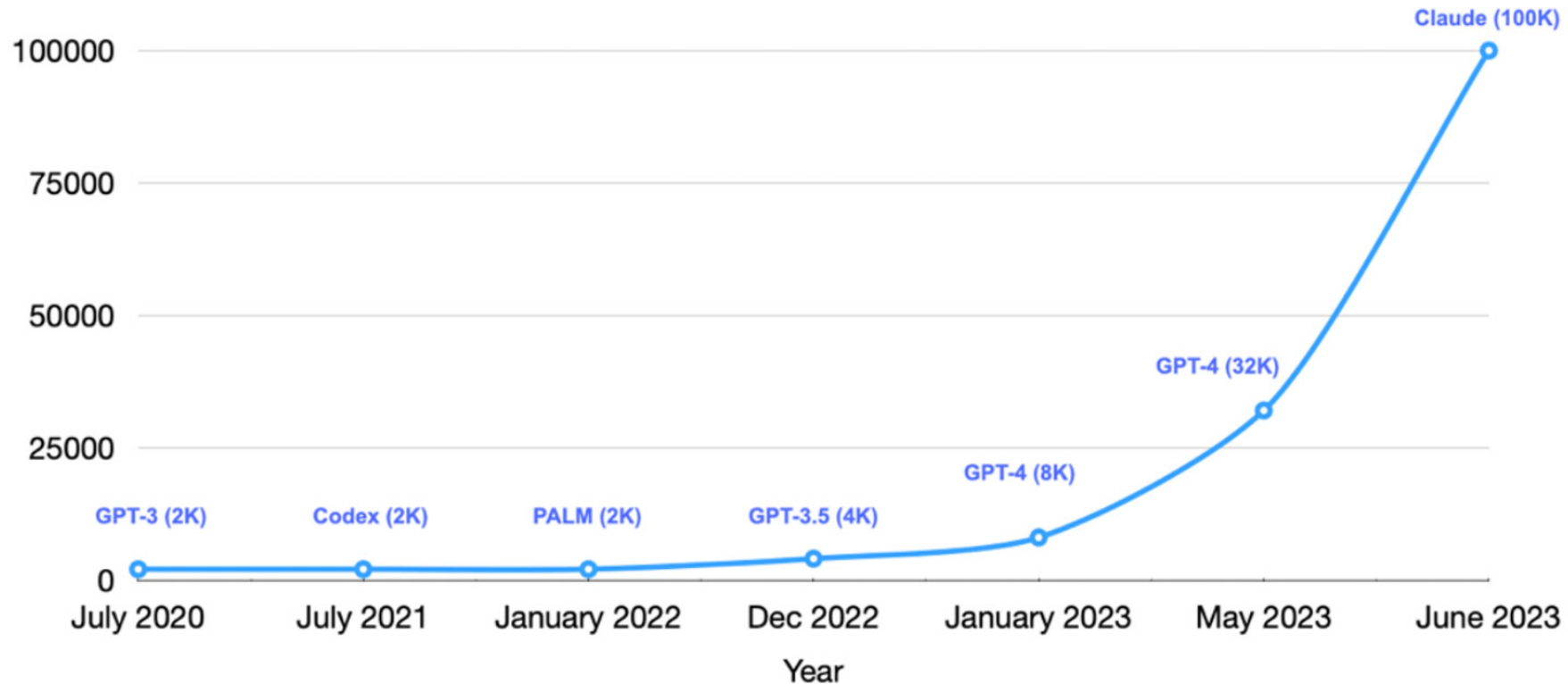
Why Transformer-based Generative Model (TbGM) Inference?

- Model size



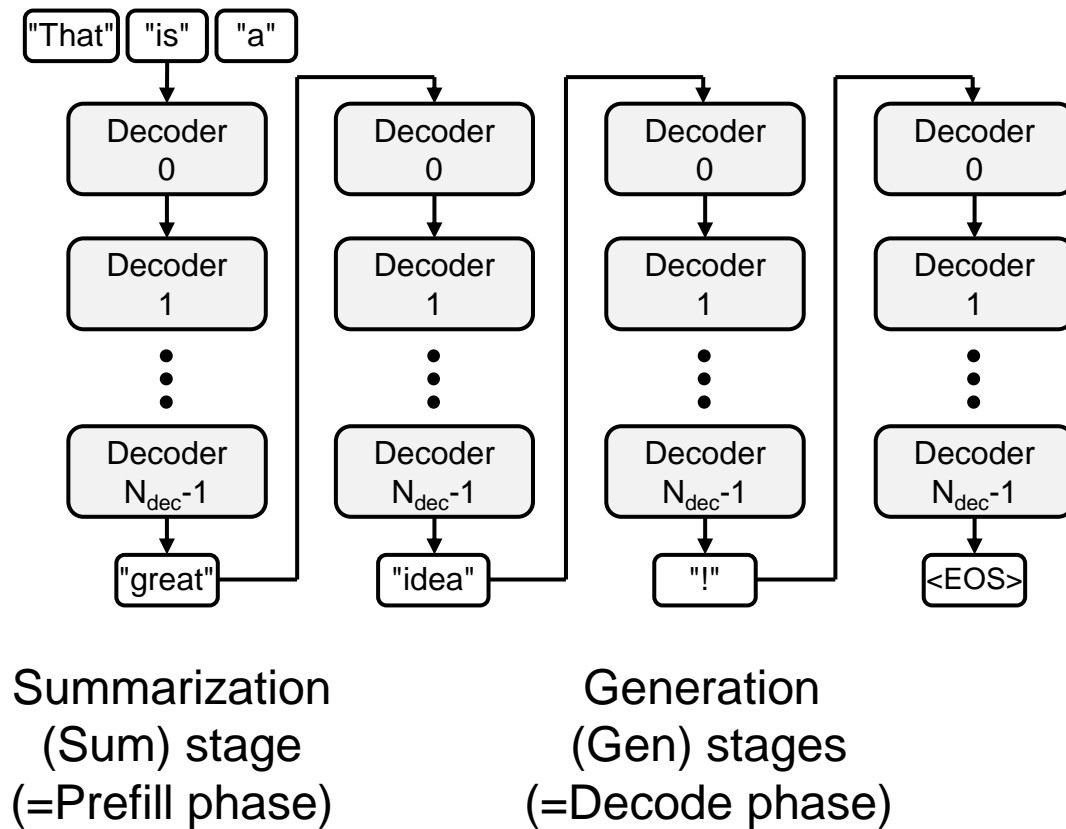
Why Transformer-based Generative Model (TbGM) Inference?

- Sequence length (L) supported by TbGM

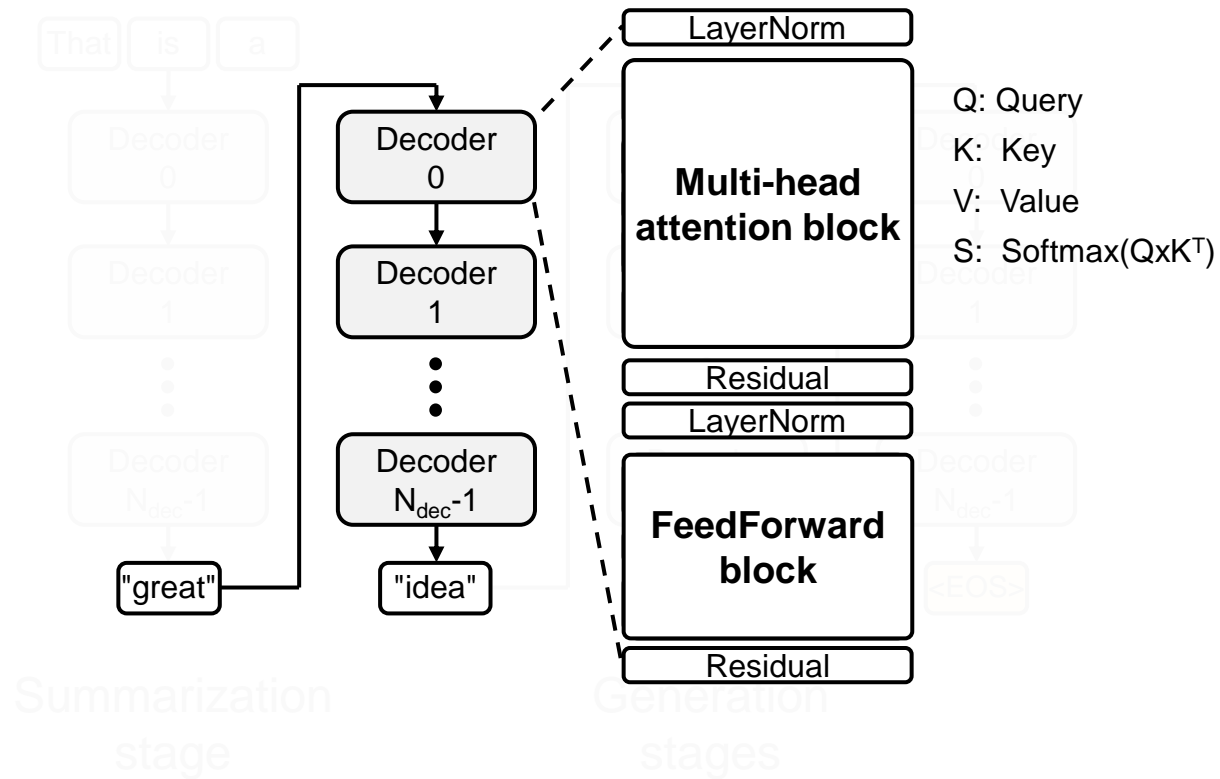


<https://hazyresearch.stanford.edu/blog/2023-03-27-long-learning>

TbGM Inference

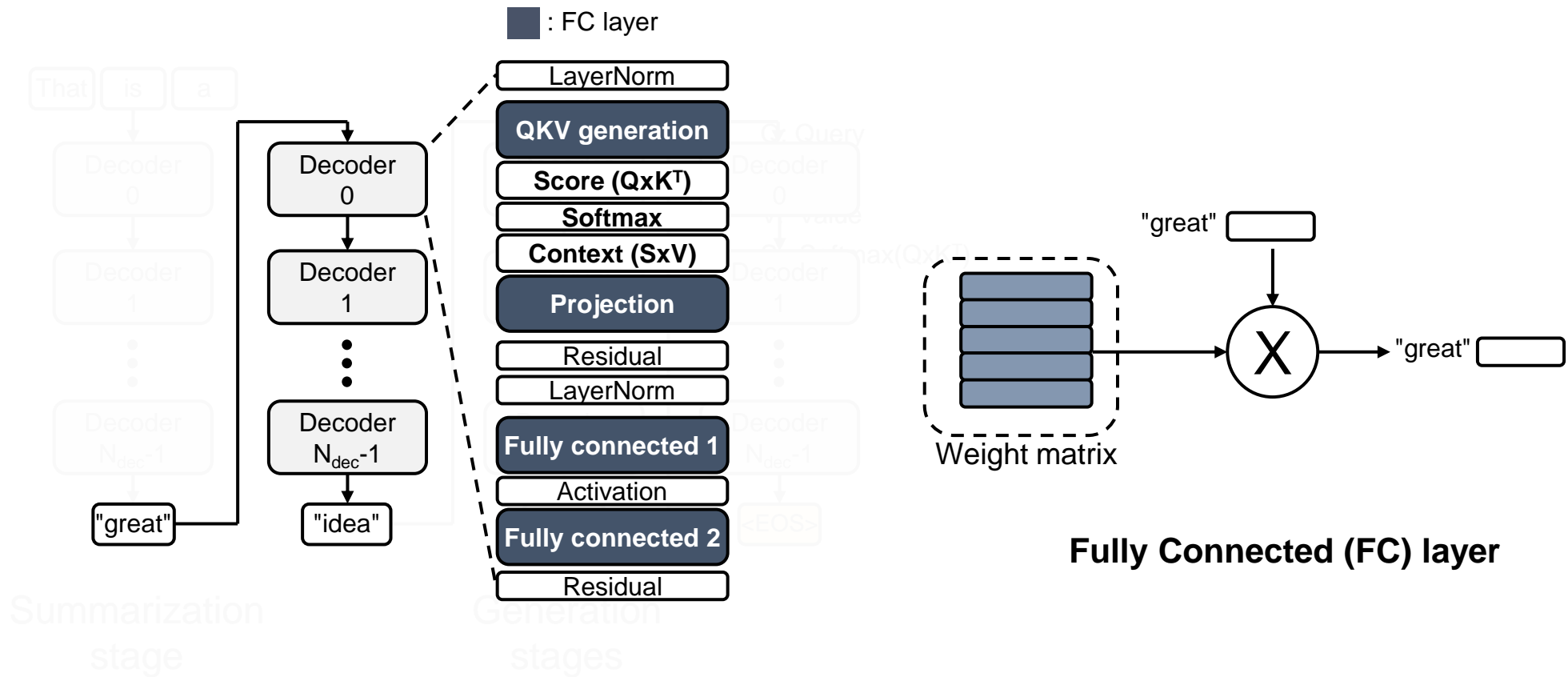


Characteristics of the Gen Stage



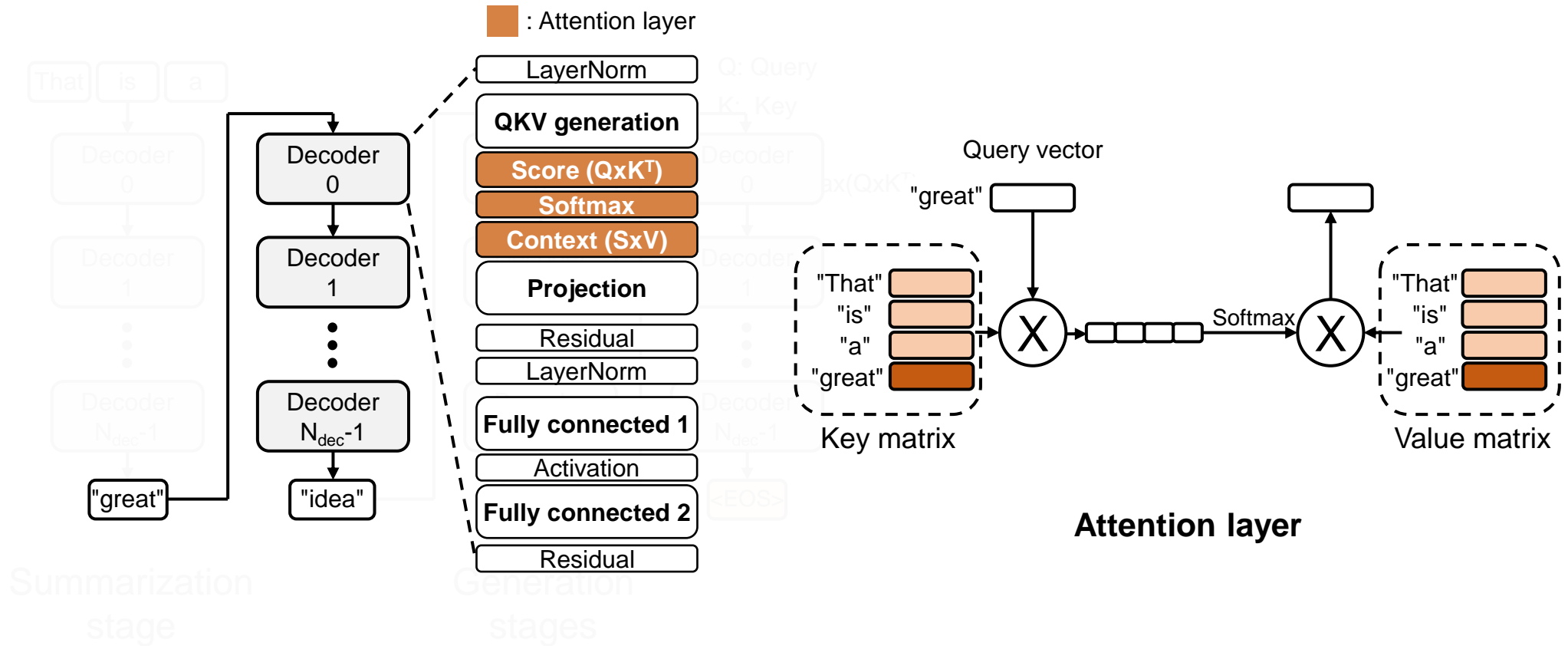
Characteristics of the Gen Stage

- **FC layers** are all **general matrix-vector multiplications (GEMVs)**



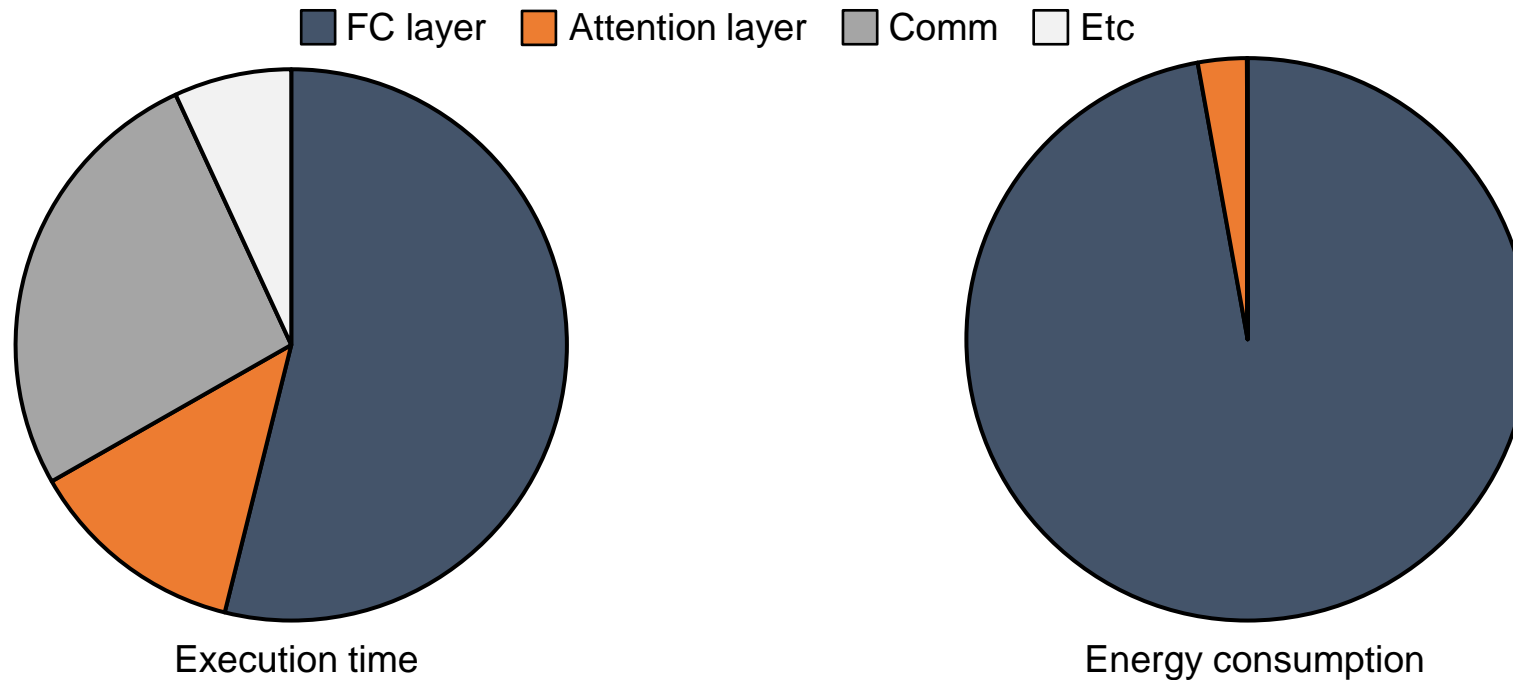
Characteristics of the Gen Stage

- The **attention layer** also has **GEMVs** ($\text{GEMV}_{\text{score}}$ and $\text{GEMV}_{\text{context}}$)



Prior TbGM Accelerators

- Many prior works [1,2,3] for TbGM accelerator focused on accelerating **FC layers**
 - FC layers account for a significant portion of execution time and energy consumption



Execution time and energy consumption breakdown of TbGM inference
(GPT3-175B on DGX-A100 with HBM3 , $L_{in}=2048$, $L_{out}=128$)

[1] S Lee et al., "Hardware Architecture and Software Stack for PIM Based on Commercial DRAM Technology," ISCA, 2021

[2] S Hong et al., "DFX: A Low-latency Multi-FPGA Appliance for Accelerating Transformer-based Text Generation," MICRO, 2022.

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Prior TbGM Accelerators

- Many prior works [1,2,3] for TbGM accelerator focused on accelerating **FC layers**
 - FC layers account for a significant portion of execution time and energy consumption

■ FC layer ■ Attention layer ■ Comm ■ Etc

However, a key assumption so far is that the batch size is 1



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Outline

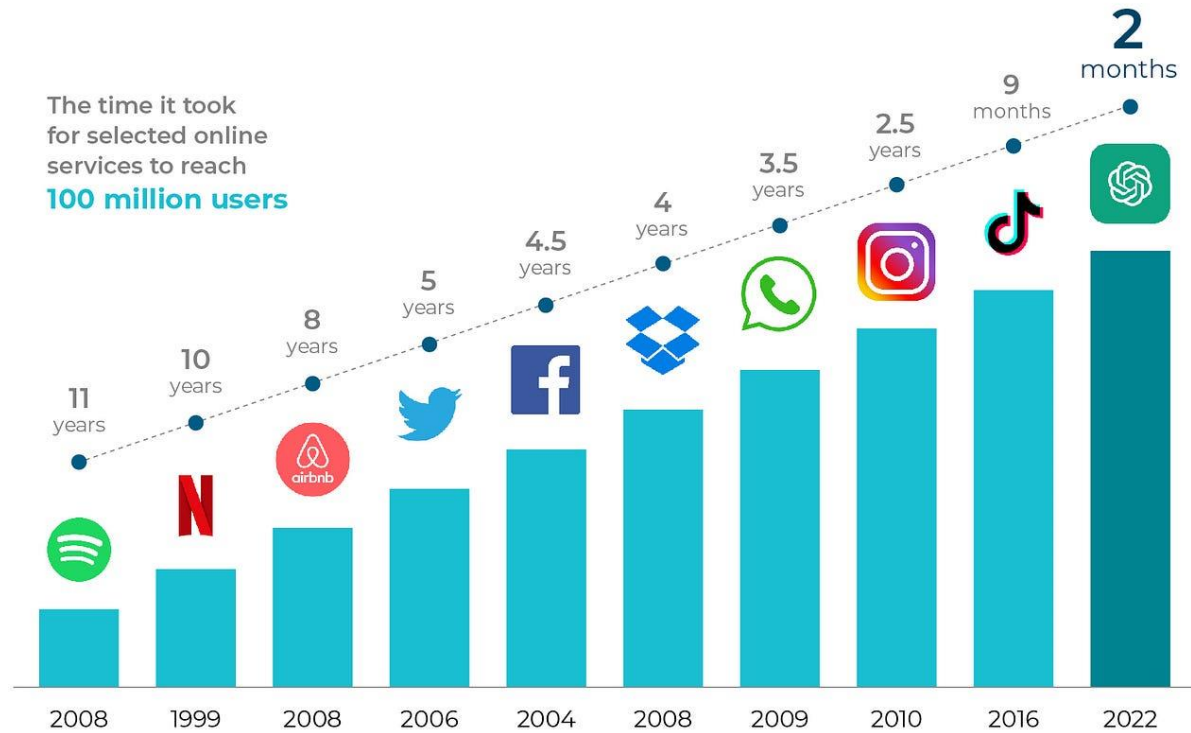
- We discover that **the attention layer**
 - becomes more important in batched TbGM inference
 - poses several challenges in conventional systems
- To address these challenges, we propose
 - processing-in-memory (PIM)-based accelerator (**AttAcc**) for the attention layer
 - heterogeneous system with **AttAcc** and xPU for end-to-end TbGM inference
 - optimizations that improve utilization of the heterogeneous system

Why Large Batch Size Matters

- Ensure sufficient requests from increased TbGM inference usage



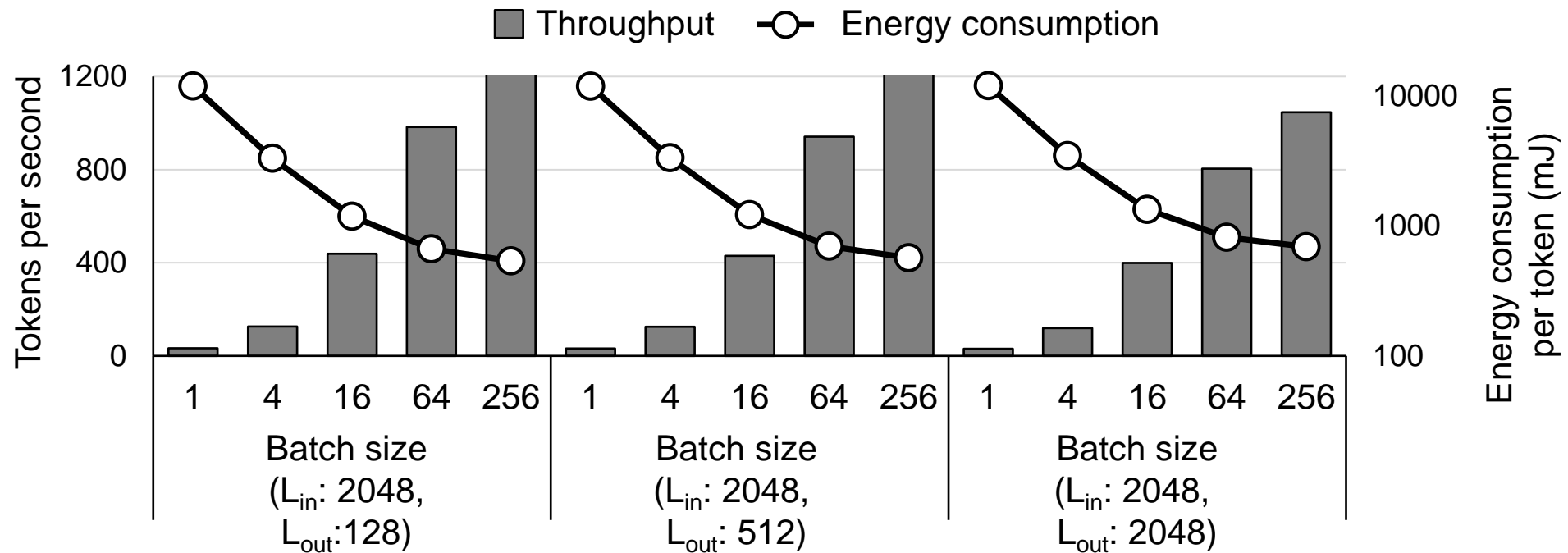
Chat-GPT sprints to 100 million users



Source: World of Statistics

Why Large Batch Size Matters

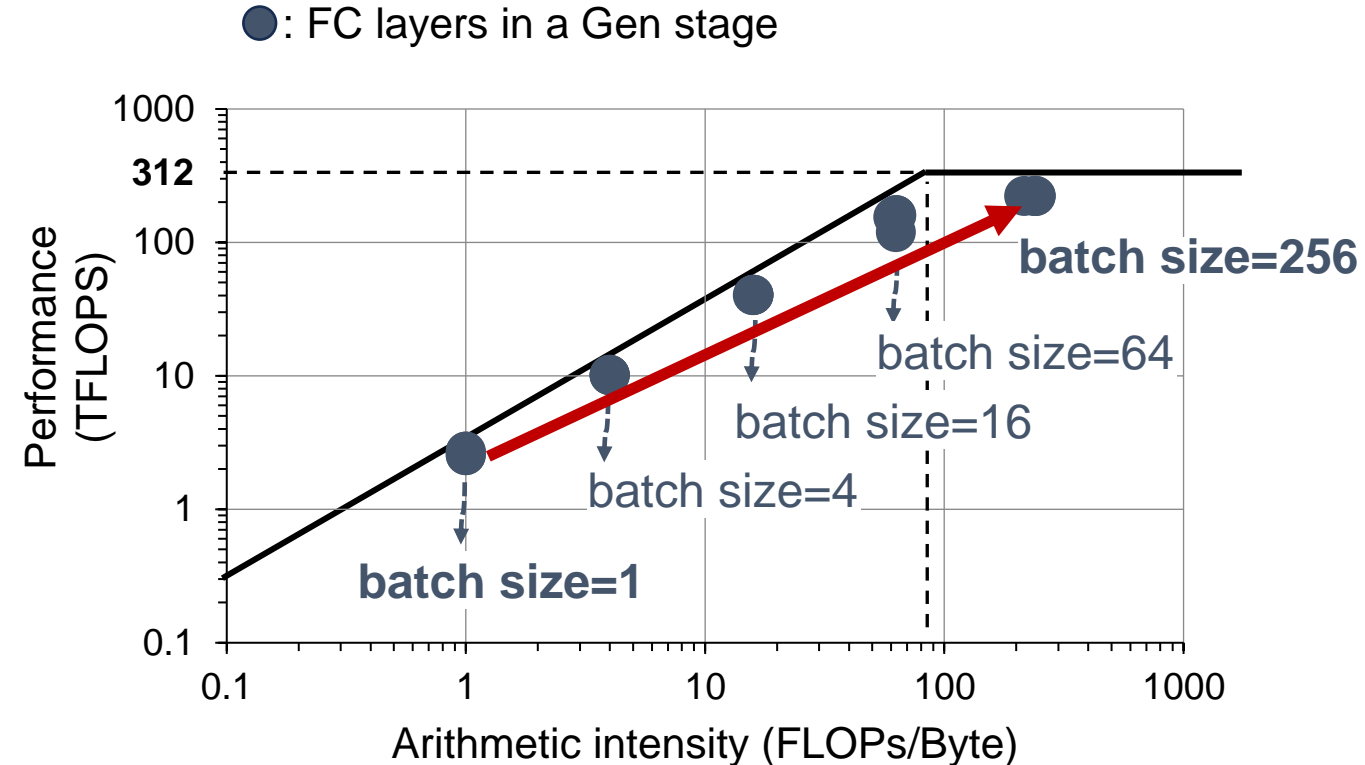
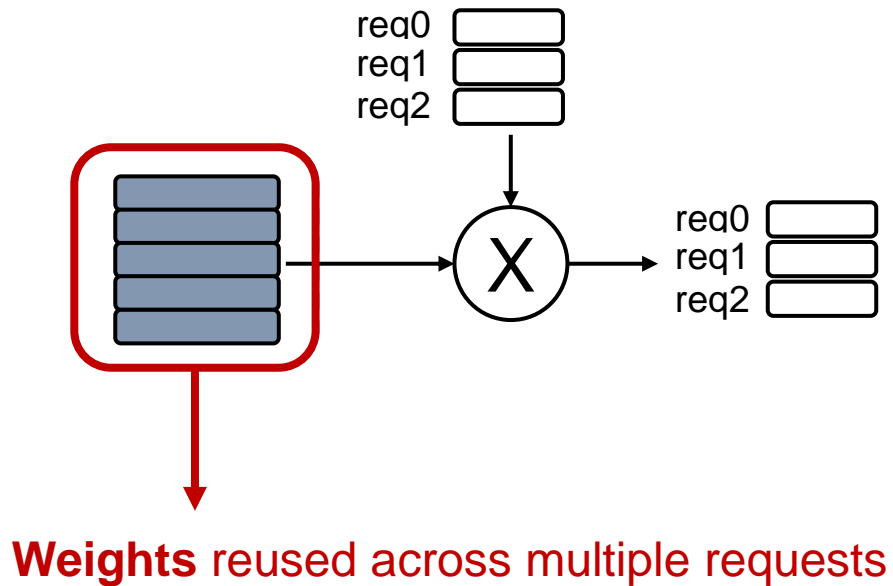
- Ensure sufficient requests from increased TbGM inference usage
- Batching technique for TbGM inference [1] enables high throughput and energy efficiency



Throughput and energy consumption per output token of TbGM inference (GPT-3 175B, DGX A100 with HBM3)

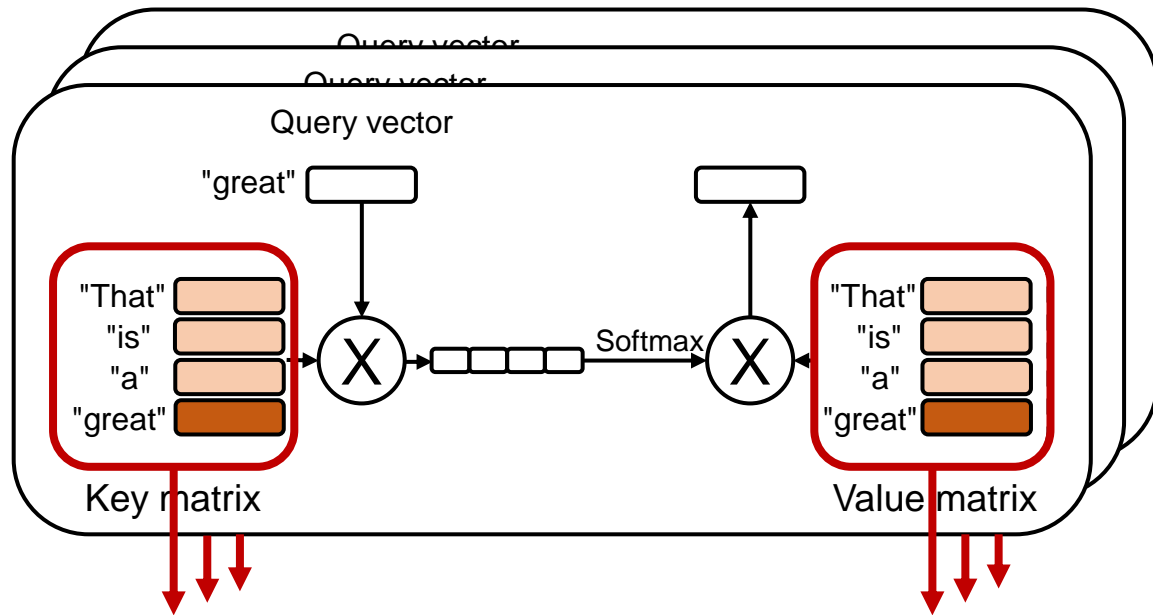
What If Batch Size Increases?

- **FC layers** become more **compute-intensive**
 - Weight matrices are shared across different requests

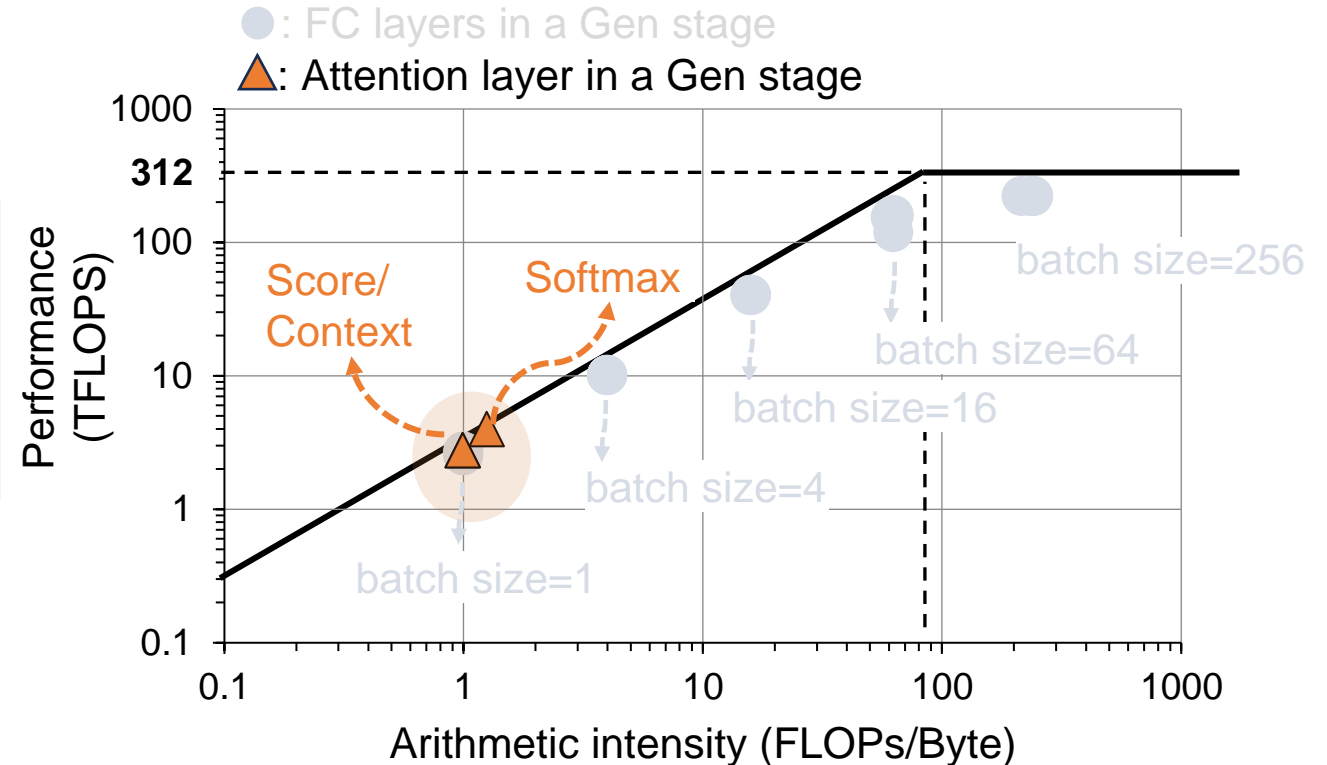


What If Batch Size Increases?

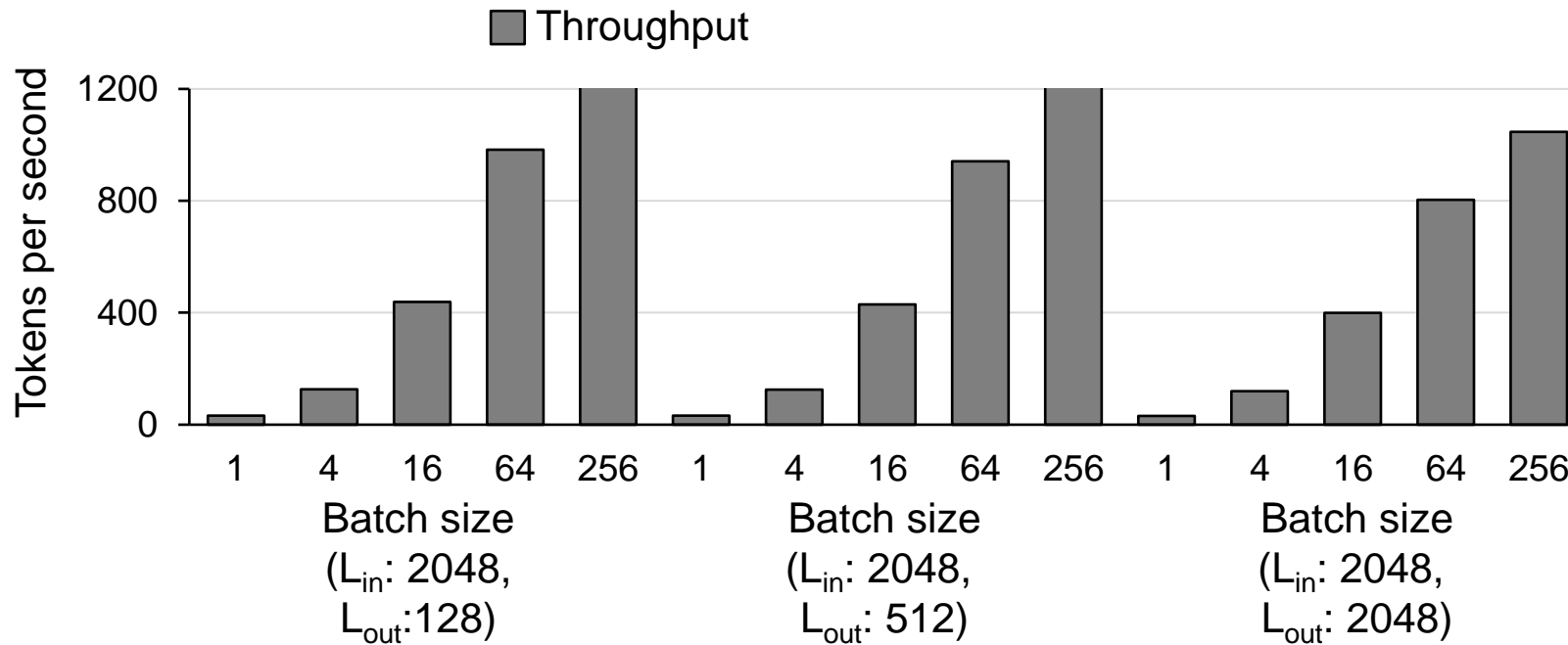
- The attention layer is still **memory-intensive**
 - The attention layer has unique **KV matrices per request**
 - The arithmetic intensity **remains nearly 1** regardless of the batch size



Key and Value (KV) matrices per request



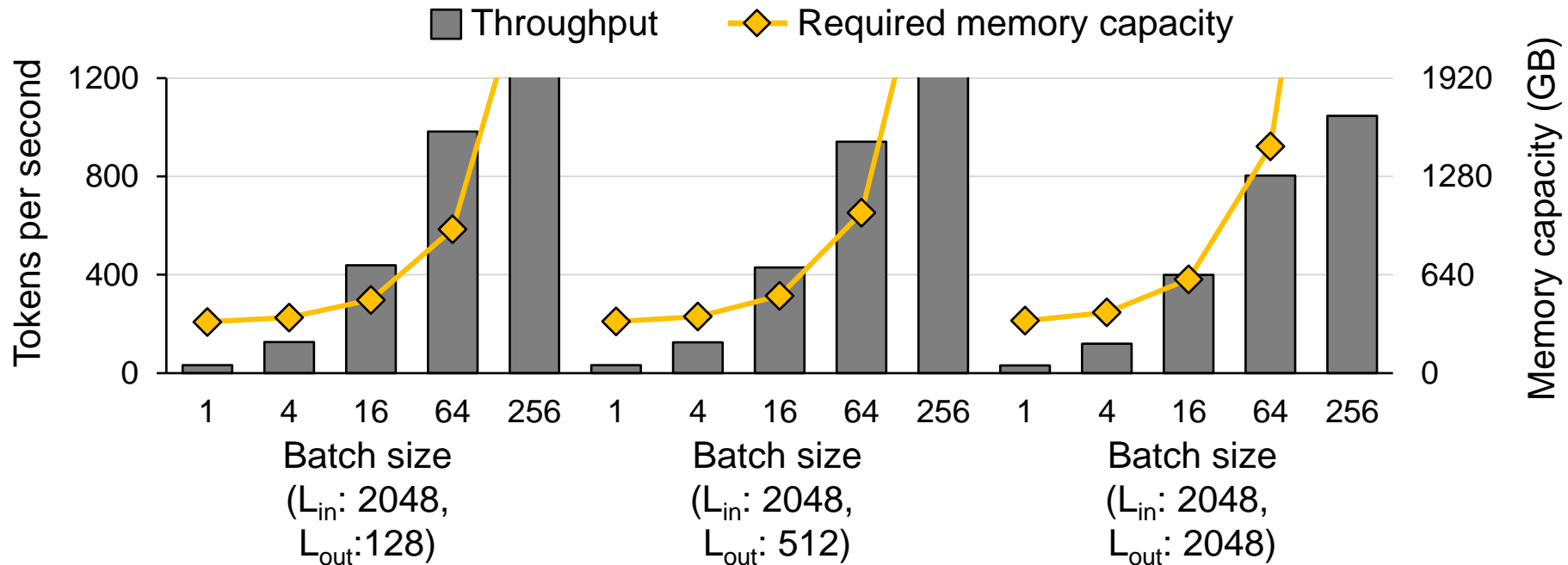
Challenges of Large Batch Size on Conventional Systems



Throughput per output token of TbGM inference
(GPT-3 175B, DGX A100 with HBM3)

Challenges of Large Batch Size on Conventional Systems

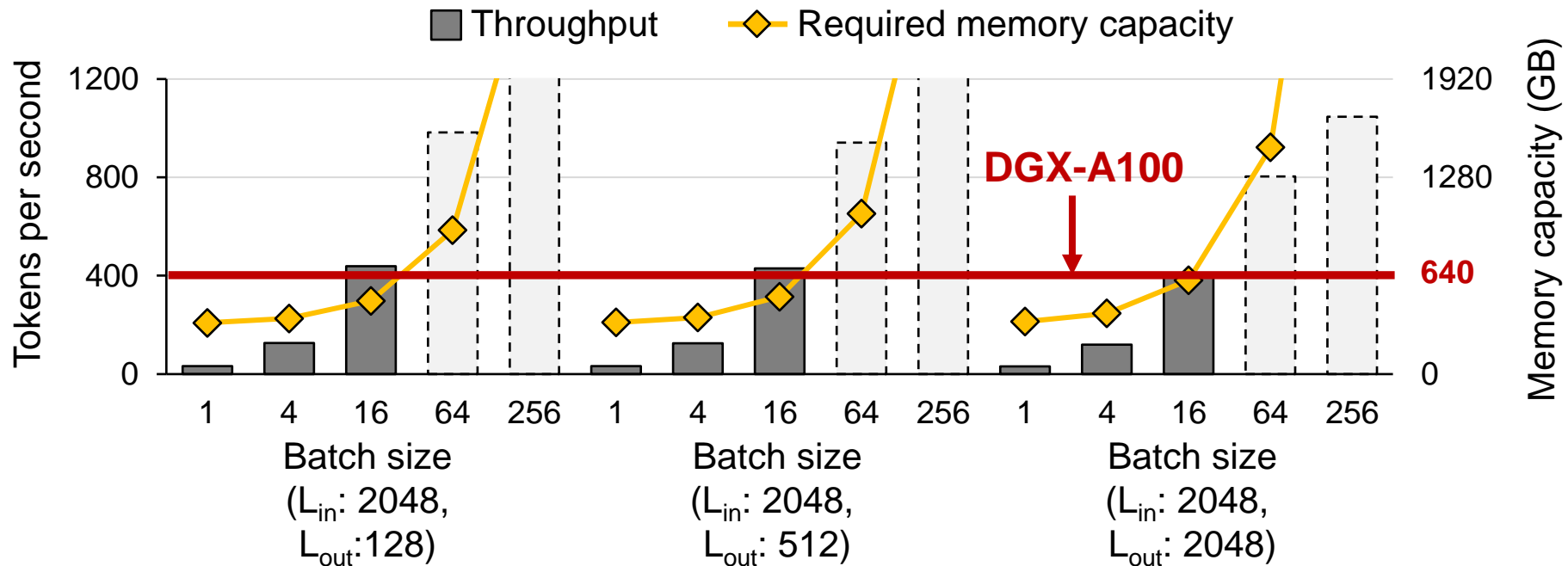
- **Large memory capacity requirement** from KV matrices
 - KV matrices require more memory capacity in proportion to batch size.



Throughput and required memory capacity per output token of TbGM inference
(GPT-3 175B, DGX A100 with HBM3)

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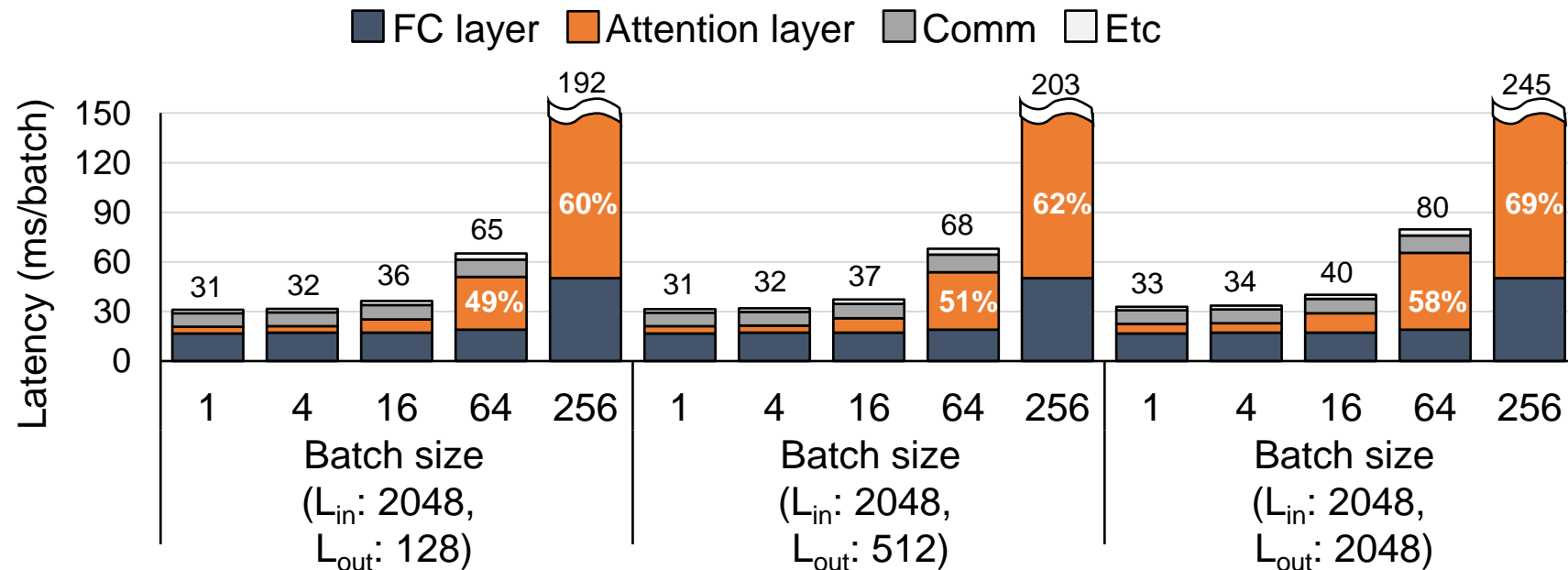
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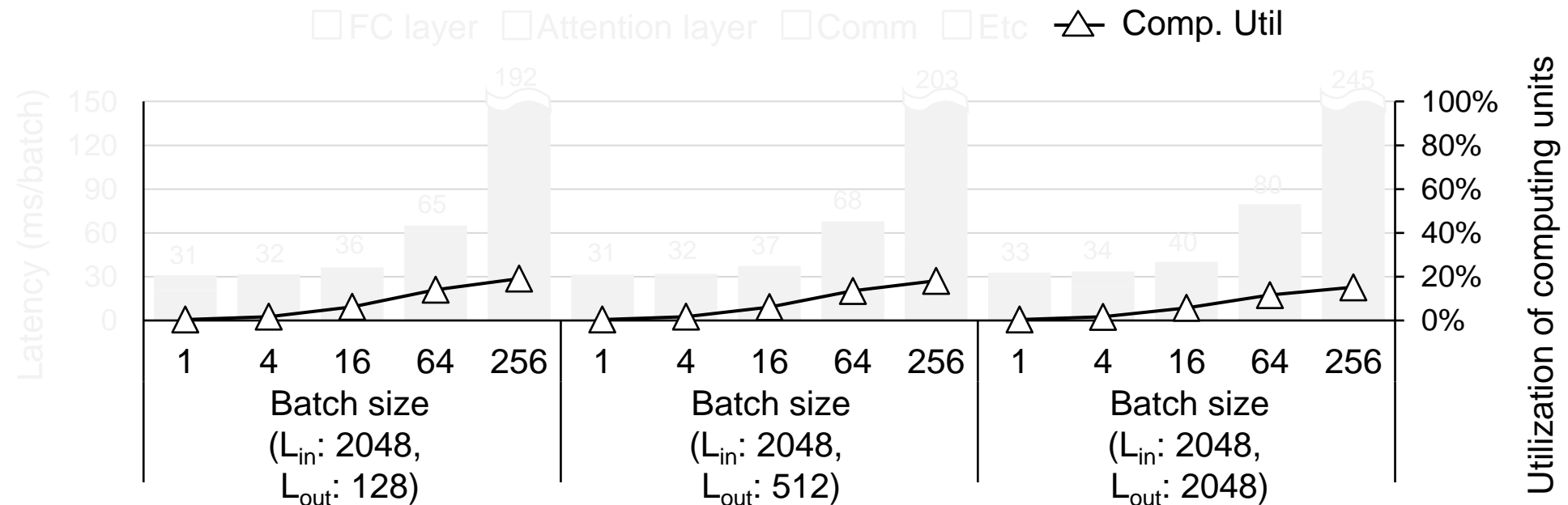
- **Long latency** of the attention layer
 - The latency of the attention layer increases linearly with batch size.
 - It can limit batch sizes under service level objectives (SLOs).



The Gen stage time breakdown and compute utilization
(GPT-3 175B, DGX-unlimited memory capacity)

Challenges of Large Batch Size on Conventional Systems

- Low utilization of computing units from attention layer



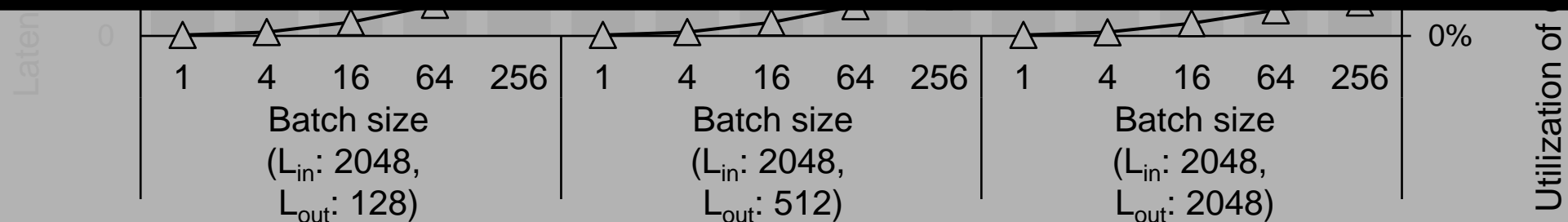
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Challenges of Large Batch Size on Conventional Systems

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□ FC layer □ Attention layer □ Comm □ Etc -△- Comp. Util

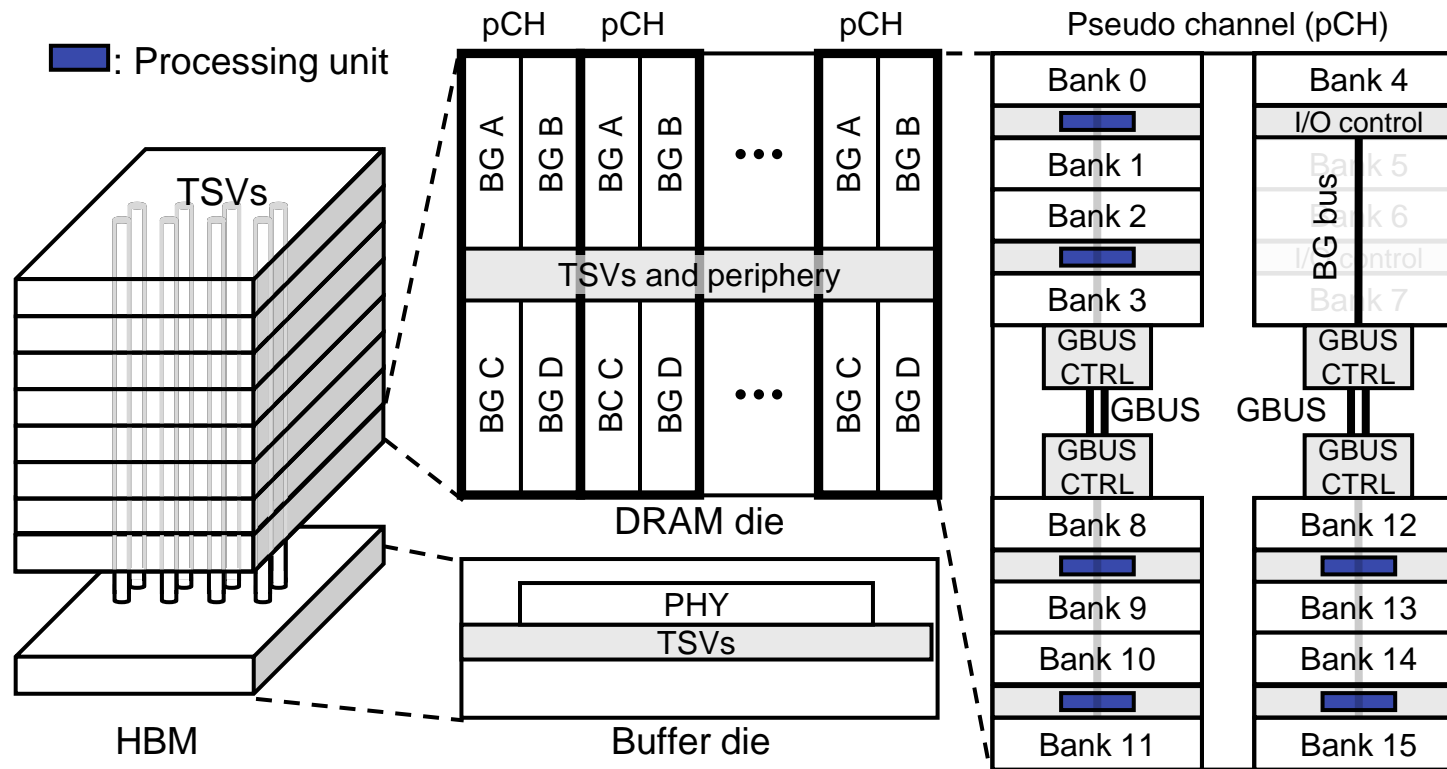
We propose Processing-in-Memory (PIM)-based accelerator for the attention layer



The Gen stage time breakdown and compute utilization
(GPT-3 175B, DGX-unlimited memory capacity)

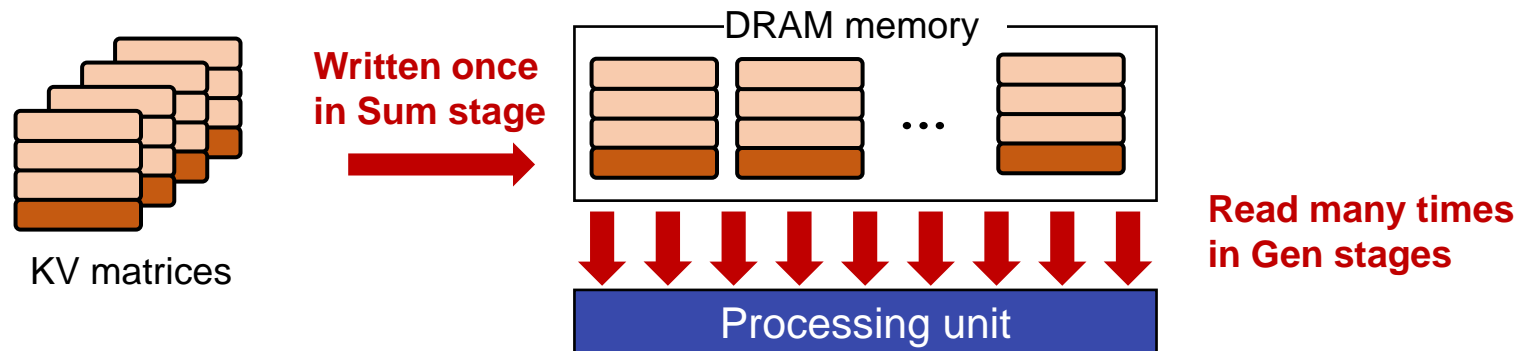
Processing-In-Memory (PIM)

- PIM exploits abundant internal bandwidth to processing units (PUs) closer to the memory.



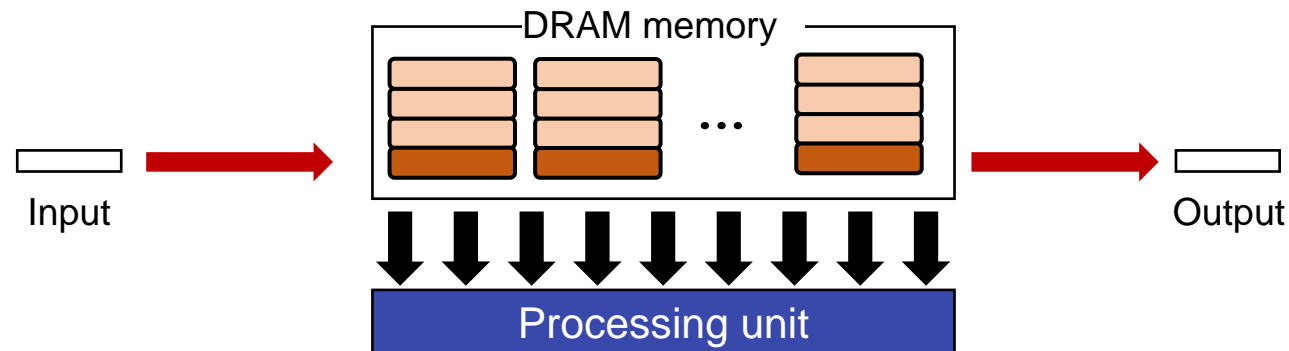
Why Processing-In-Memory (PIM) for the Attention Layer?

- High memory bandwidth requirement
 - The attention layer is **memory-intensive GEMV**
 - The size of the KV matrices is **too large to be cached**
- Relatively low external bandwidth requirement
 - KV matrices are **written once** in the Sum stage and **read many times** in Gen stages



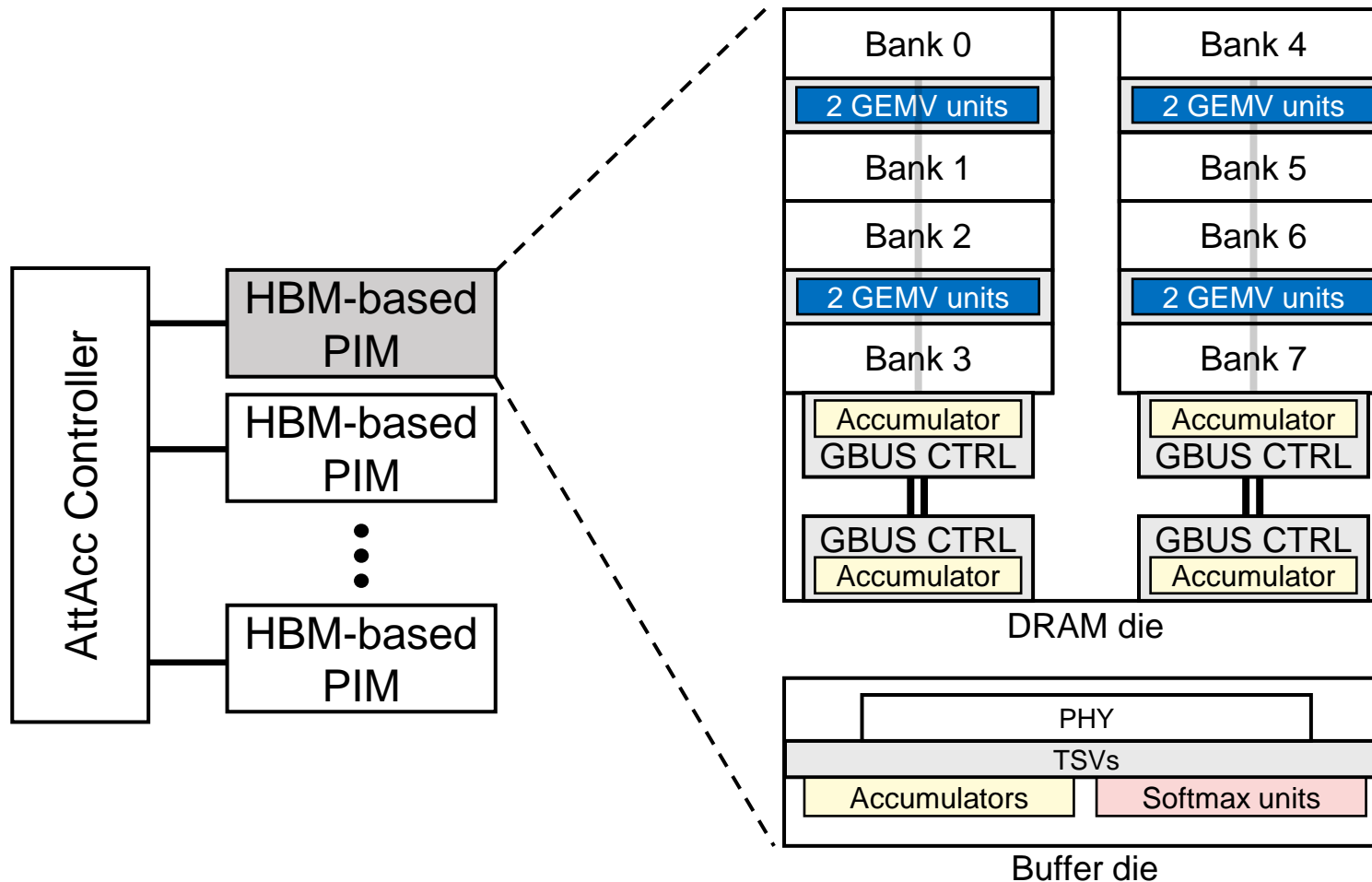
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 - KV matrices are **written once** in the Sum stage and **read many** times in Gen stages
 - The input and output of the attention layer are vectors that are **much smaller than KV matrices**.



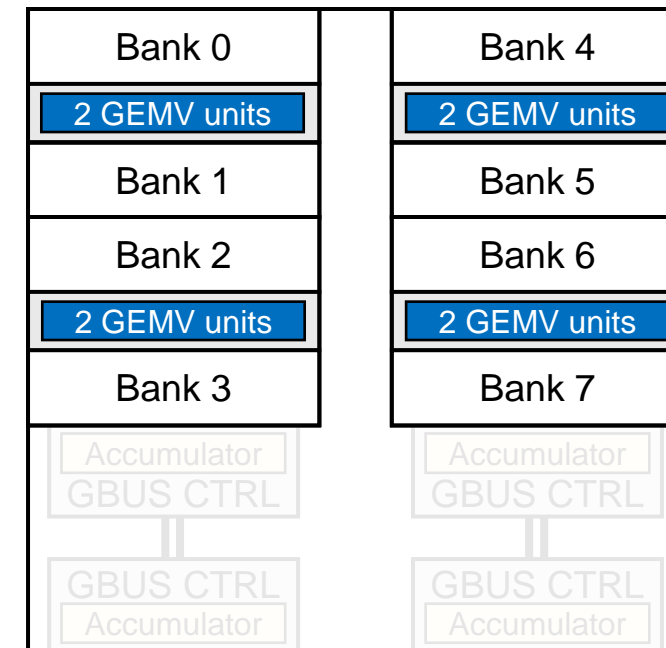
AttAcc: PIM-based Attention Accelerator

- We propose **AttAcc**, which consists of HBM-based PIMs and a controller
- HBM-based PIM has
 - GEMV units
 - Softmax unit
 - Accumulators



AttAcc: GEMV Unit

- Placed on each bank similar to Samsung HBM-PIM [1] and Hynix AiM [2]



DRAM die



Buffer die

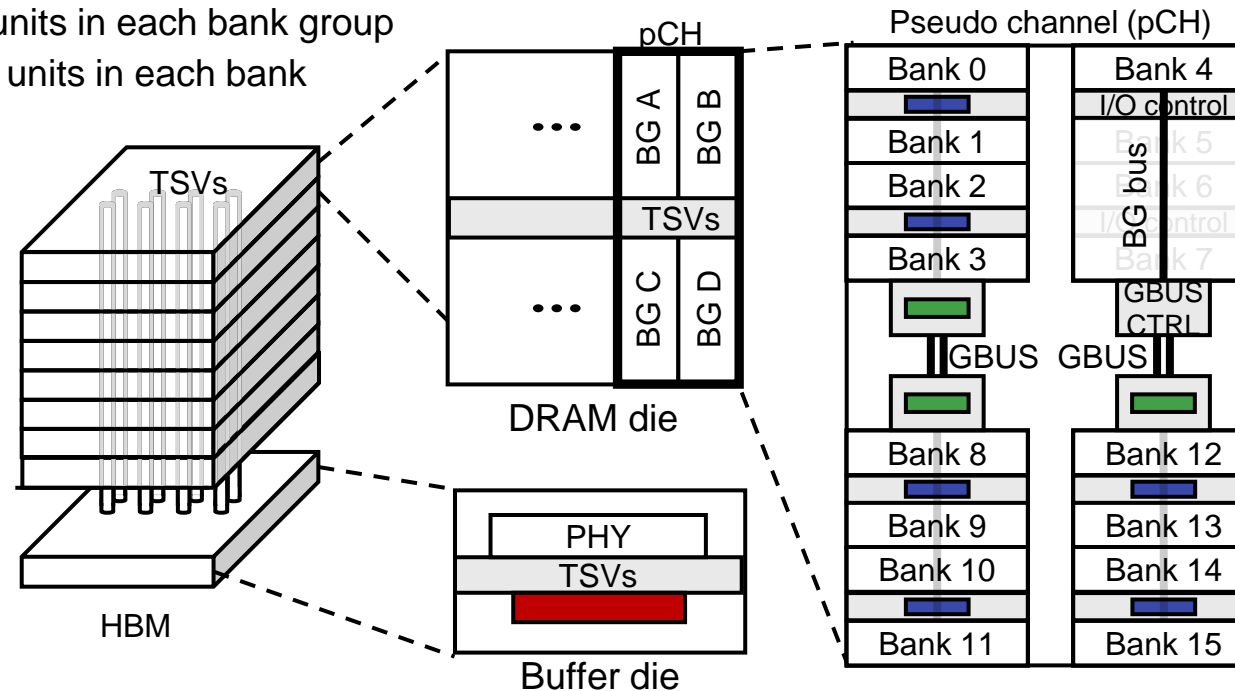
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AttAcc: GEMV Unit

- Placed on each bank similar to Samsung HBM-PIM [1] and Hynix AiM [2]
 - $AttAcc_{Buffer}$ vs $AttAcc_{BG}$ vs $AttAcc_{Bank}$

- $AttAcc_{buffer}$: GEMV units in each pCH of buffer die
- $AttAcc_{BG}$: GEMV units in each bank group
- $AttAcc_{bank}$: GEMV units in each bank

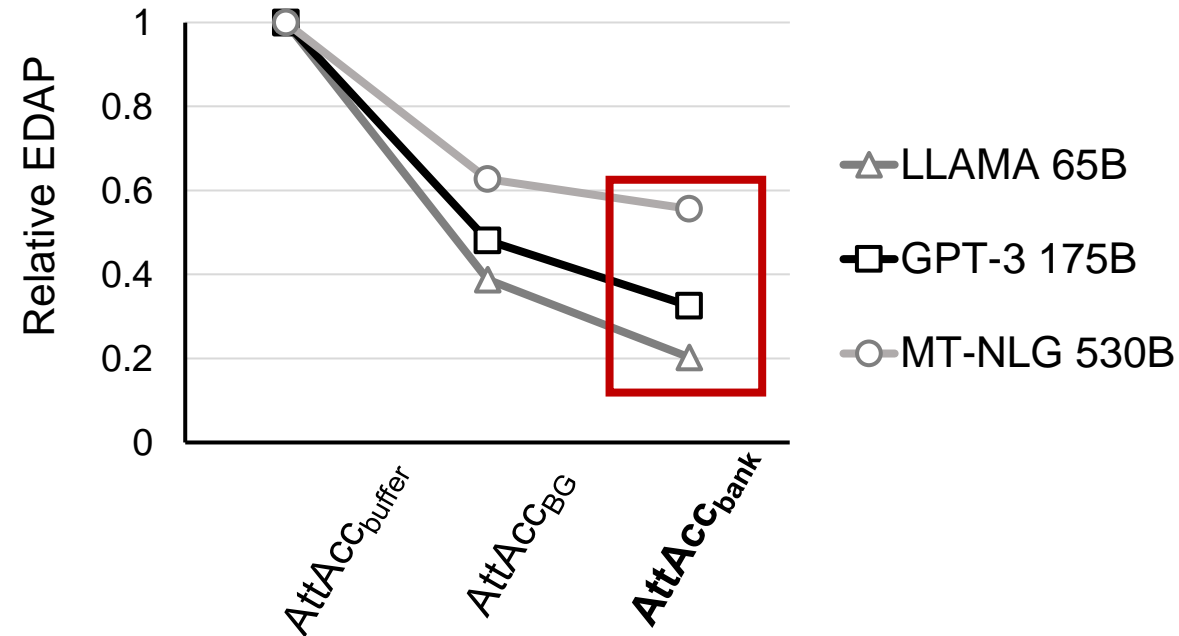


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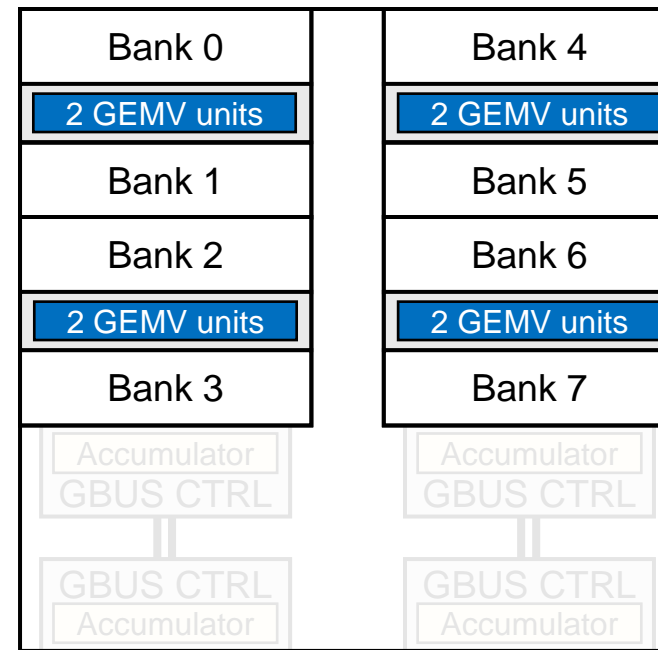
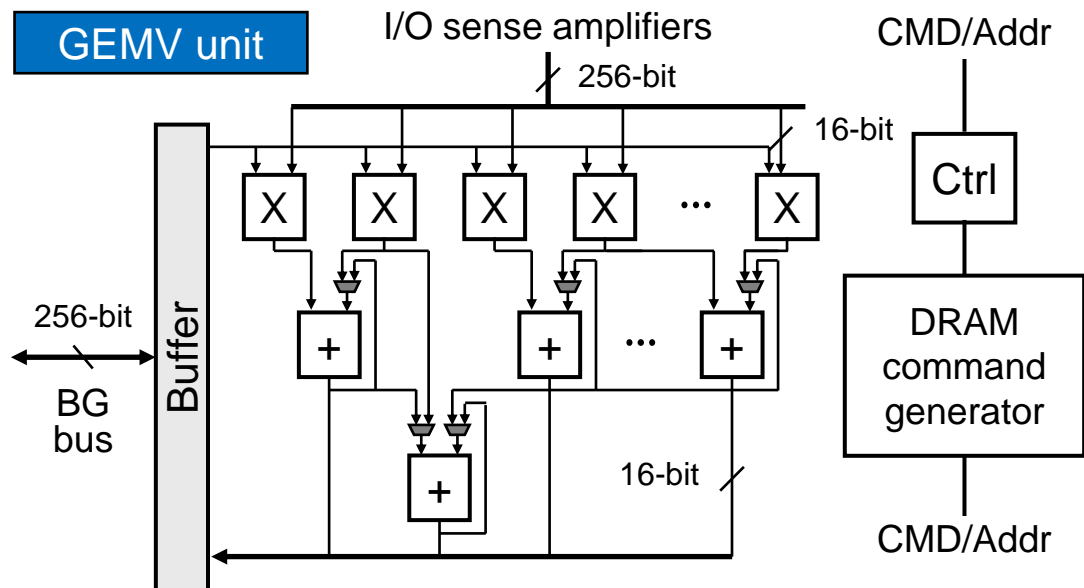


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AttAcc: GEMV Unit

- Placed on each bank similar to Samsung HBM-PIM [1] and Hynix AiM [2]
- FP16 multipliers, FP16 adders, buffer for input vectors, and control unit.



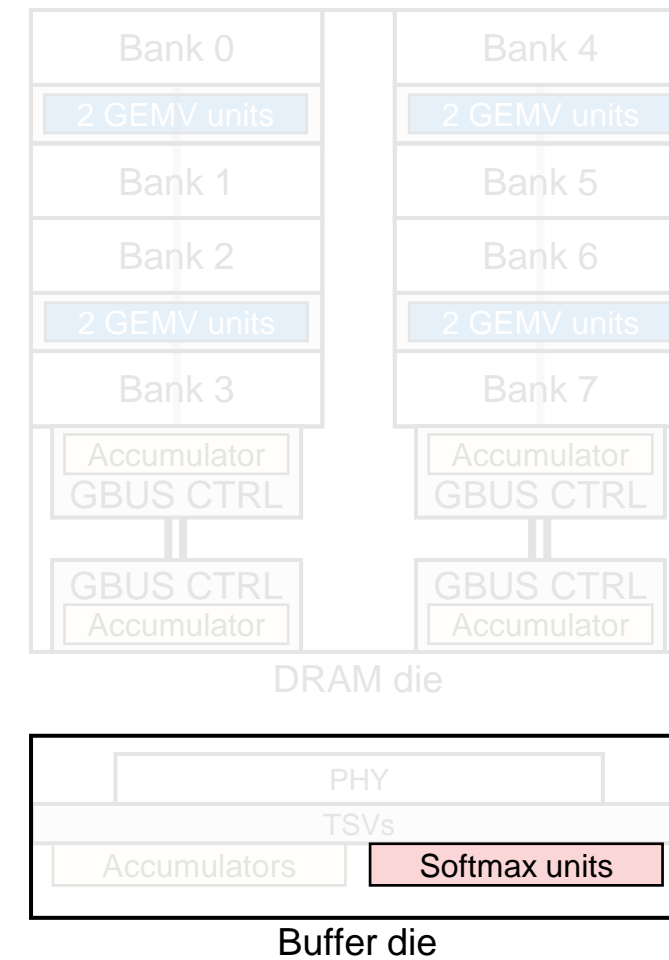
DRAM die



Buffer die

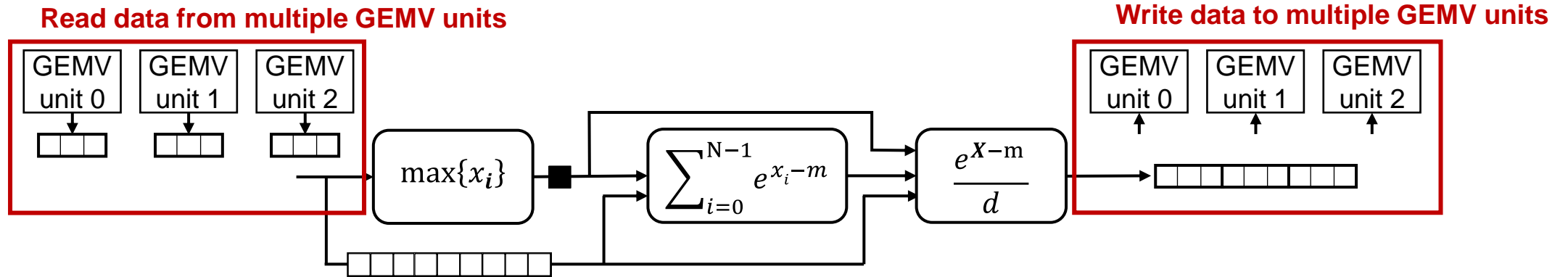
AttAcc: Softmax Unit

- Placed on buffer die



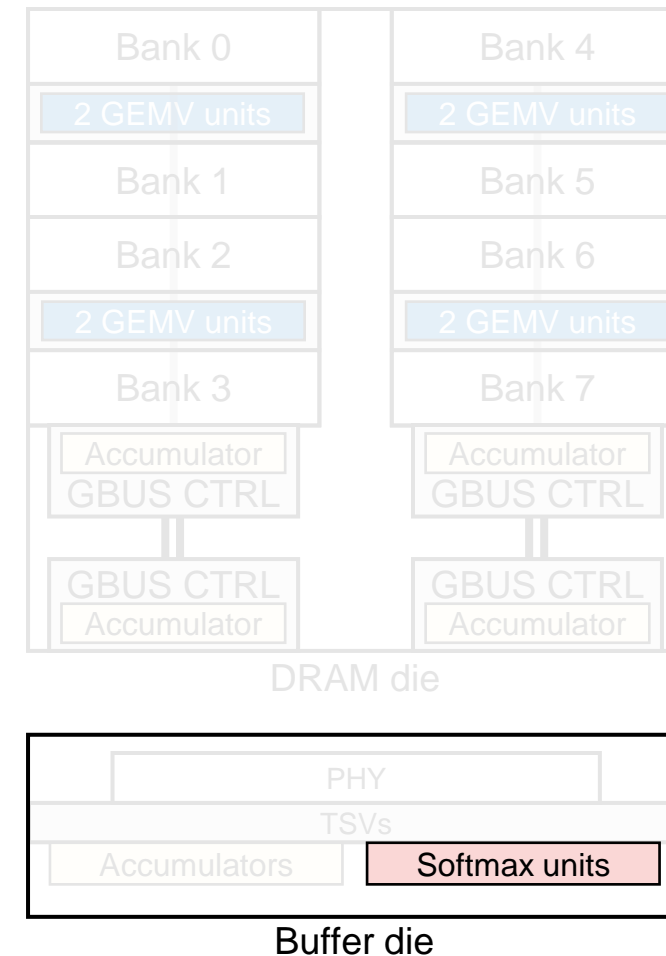
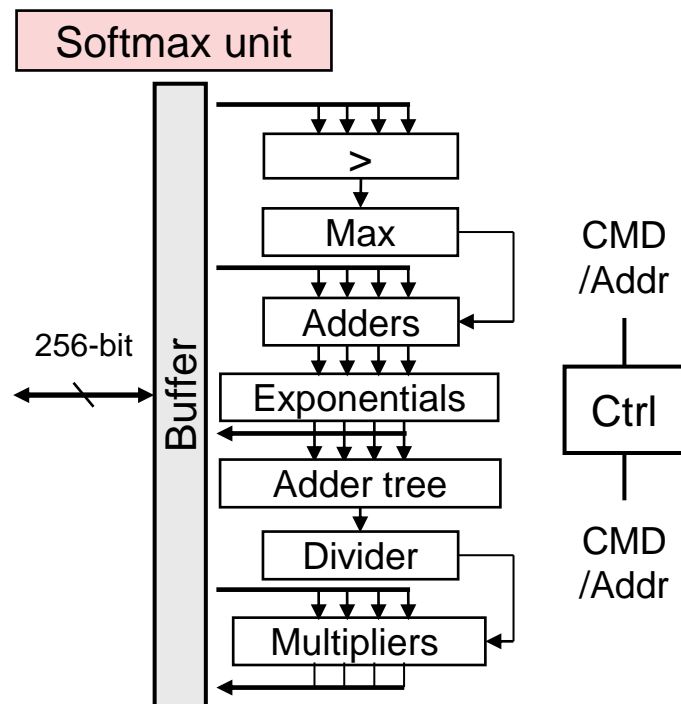
AttAcc: Softmax Unit

- Placed on buffer die
 - Communication with multiple GEMV units is required
 - Complex processing units and requirement for large SRAM buffers for intermediate vectors
 - Placing softmax unit on DRAM die is overkill.
 - = For GPT-3 175B, the FLOPs of softmax is **50 times smaller** than GEMVs in the attention layer



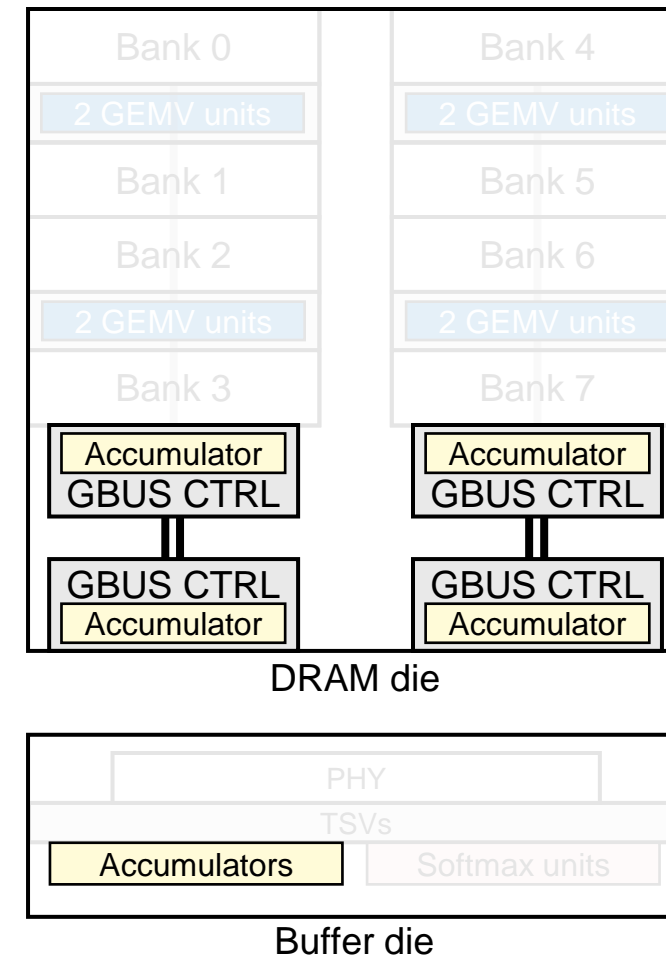
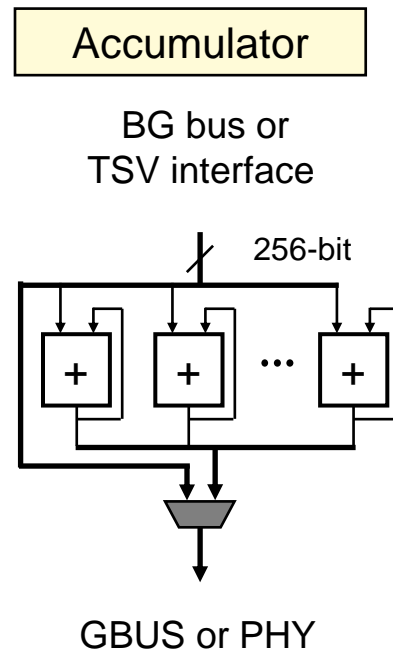
AttAcc: Softmax Unit

- Placed on buffer die
- Processing units such as exponents, multipliers, and adders supporting FP32
- Buffer for intermediate vectors and control unit.



AttAcc: Accumulator

- Placed hierarchically between the GEMV and the softmax units
- Supports the reduction of partial results from different GEMV units

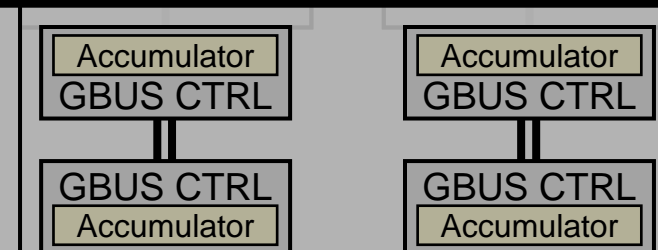
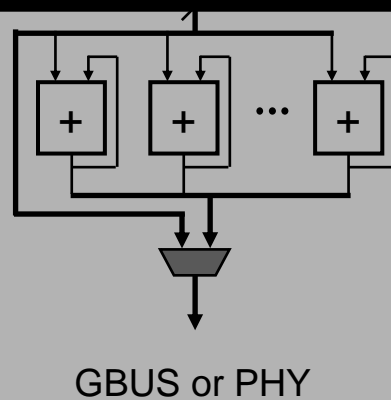


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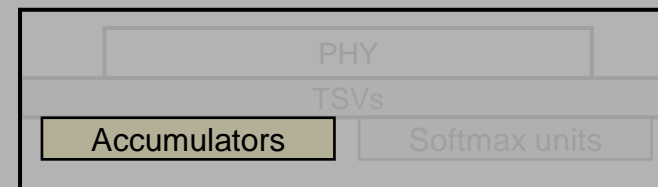
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- Supports the reduction of partial results from different GEMV units



Please refer to the full paper for more detailed design exploration and data mapping.

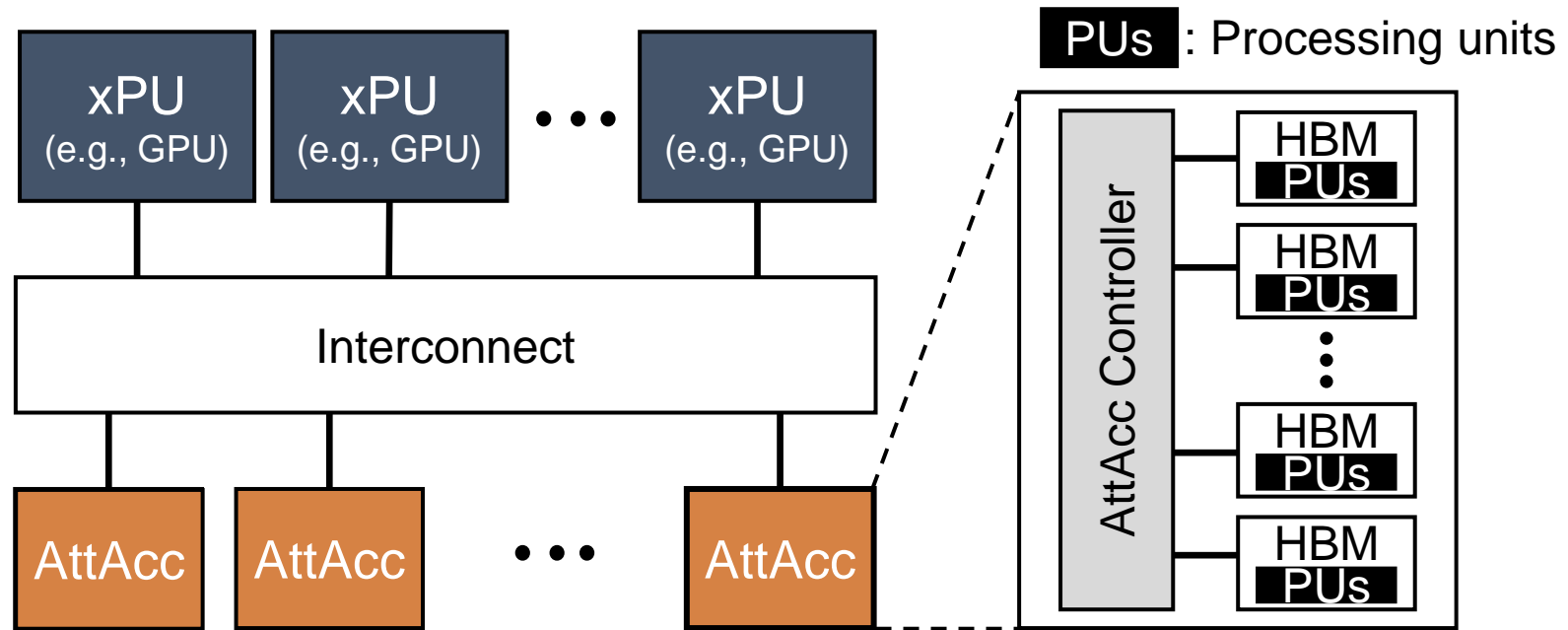


DRAM die



Buffer die

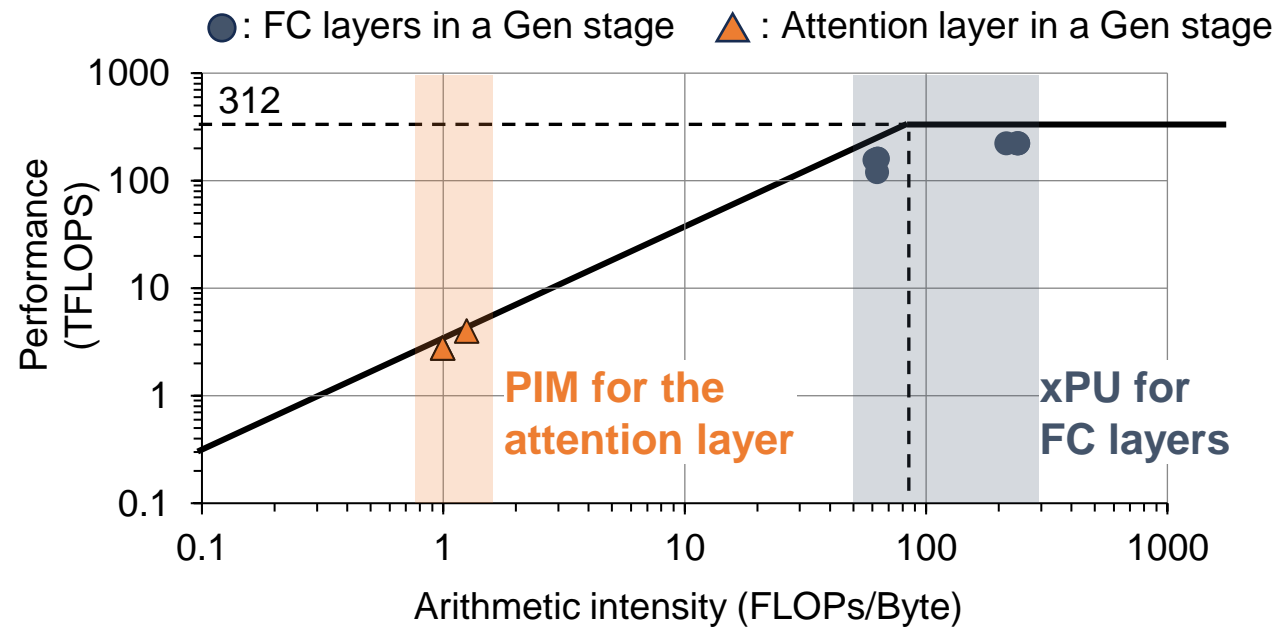
Heterogeneous System with *AttAcc*



Heterogeneous system with xPUs and *AttAccs*

Heterogeneous System with *AttAcc*

- High performance
 - High computing power of **xPU for batched FC layers** with high FLOPs/Byte
 - Amplified memory bandwidth of **PIM for the attention layer** with low FLOPs/Byte



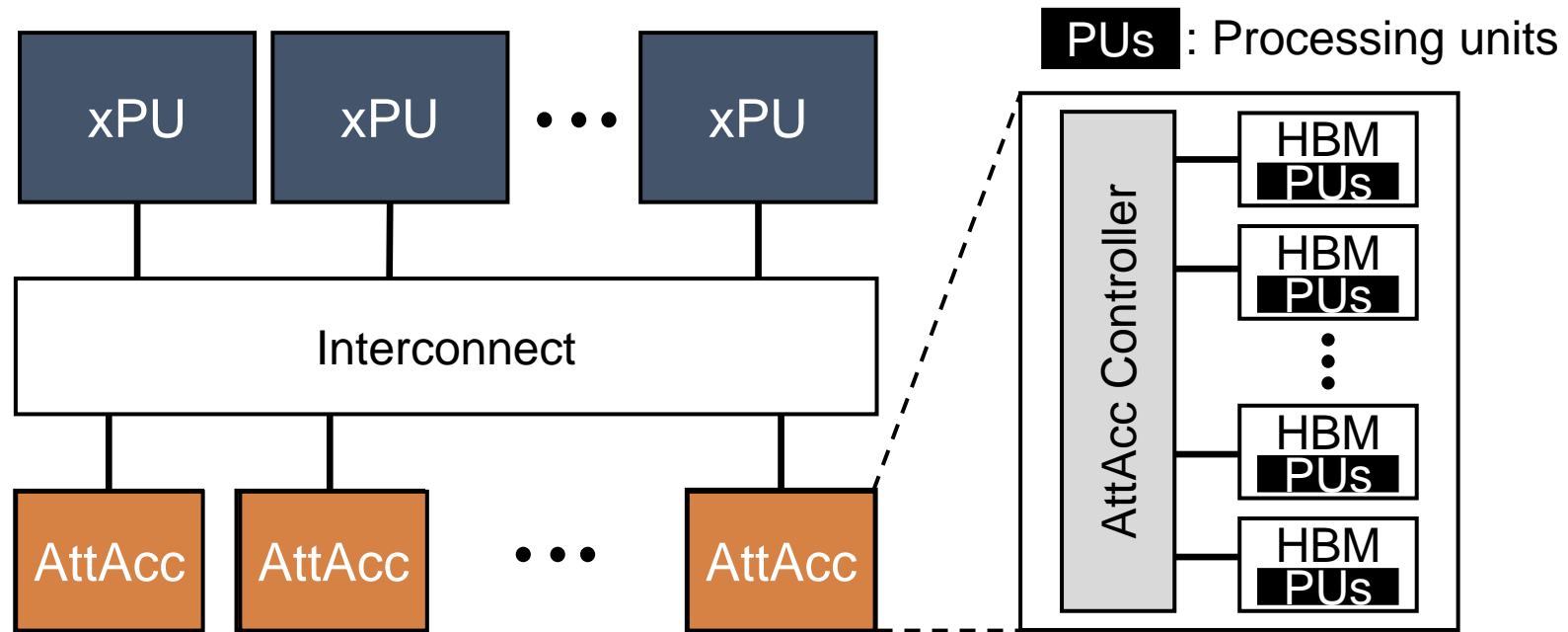
Roofline model of the DGX-A100 with HBM3

Heterogeneous System with *AttAcc*

- High performance
 - High computing power of **xPU for batched FC layers** with high FLOPs/Byte
 - Amplified memory bandwidth of **PIM for the attention layer** with low FLOPs/Byte
- High energy efficiency
 - Leveraging **high reusability of weights** of batched FC layers through on-chip caches in xPU
 - Benefit from **short data transfer** in PIM for the attention layer

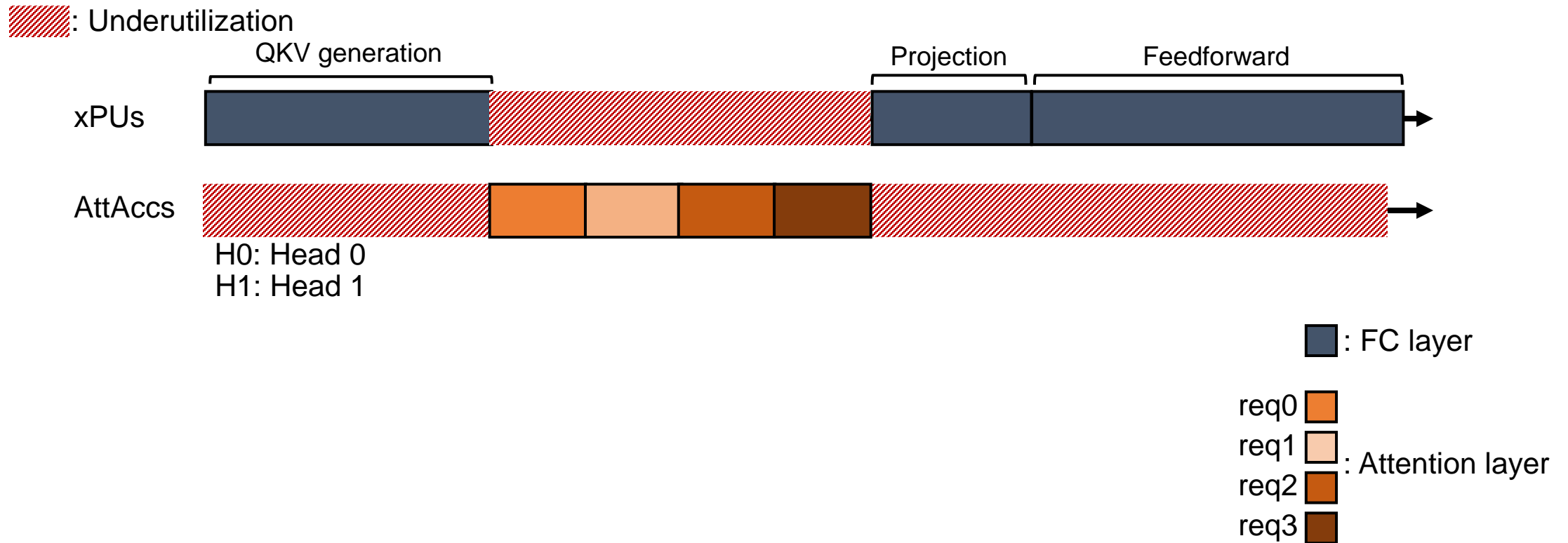
Heterogeneous System with *AttAcc*

- Proposed system consists of multiple xPUs (e.g., GPU, TPU) and attention accelerators ***AttAccs***
 - Batched FC layers on multiple xPUs
 - Attention layers on ***AttAccs***
- AttAccs*** and xPUs can be connected via an interface such as NVLINK, PCIe, and CXL.

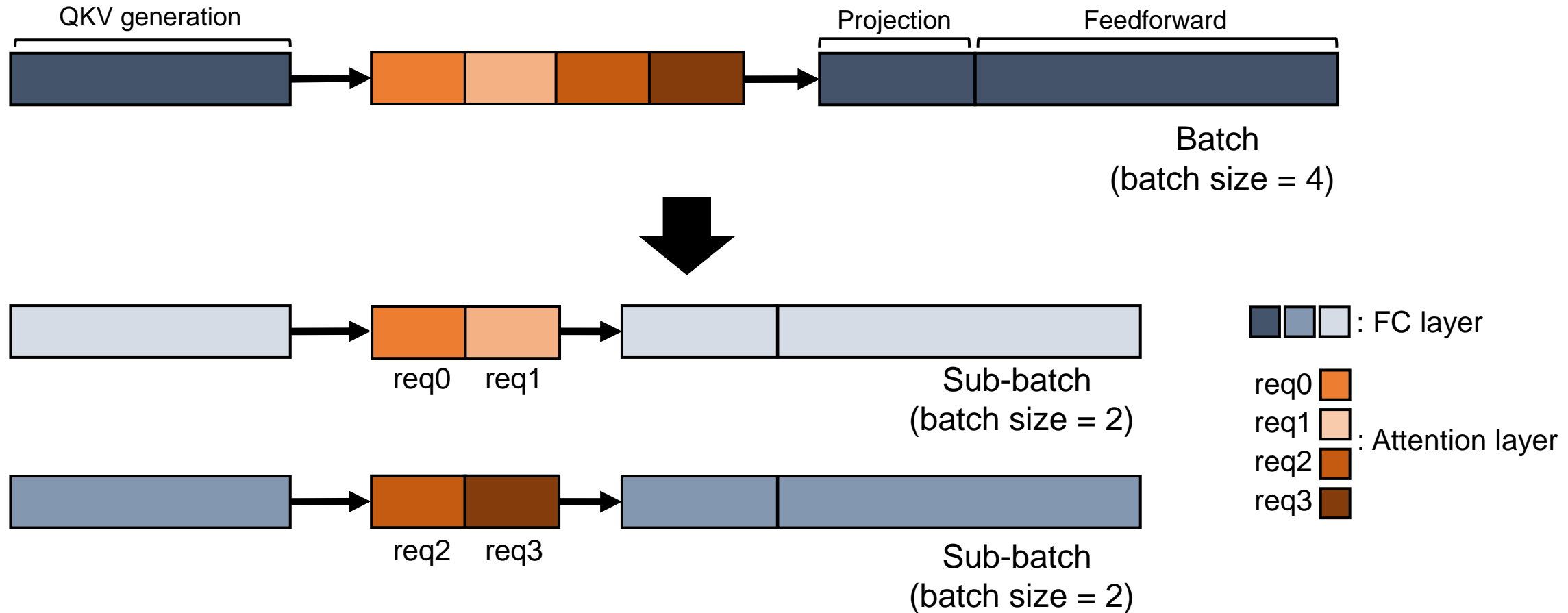


Heterogeneous system with xPUs and *AttAccs*

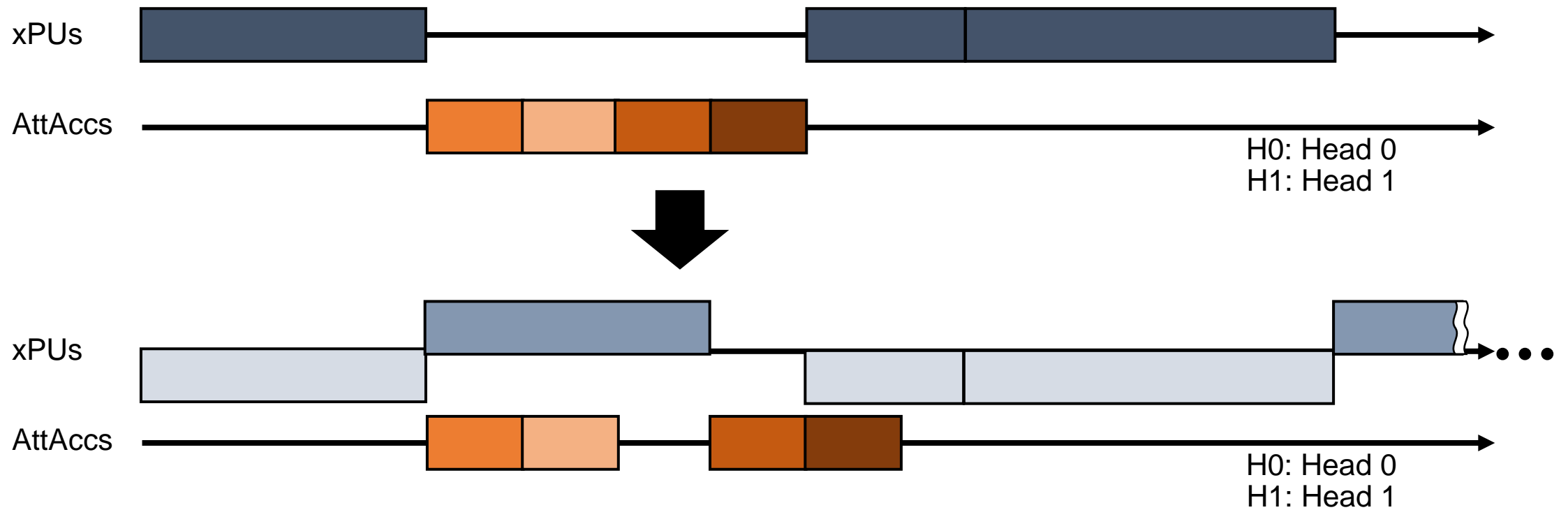
Execution Flow of the Heterogeneous System



Naïve Approach: Batch-level Pipelining

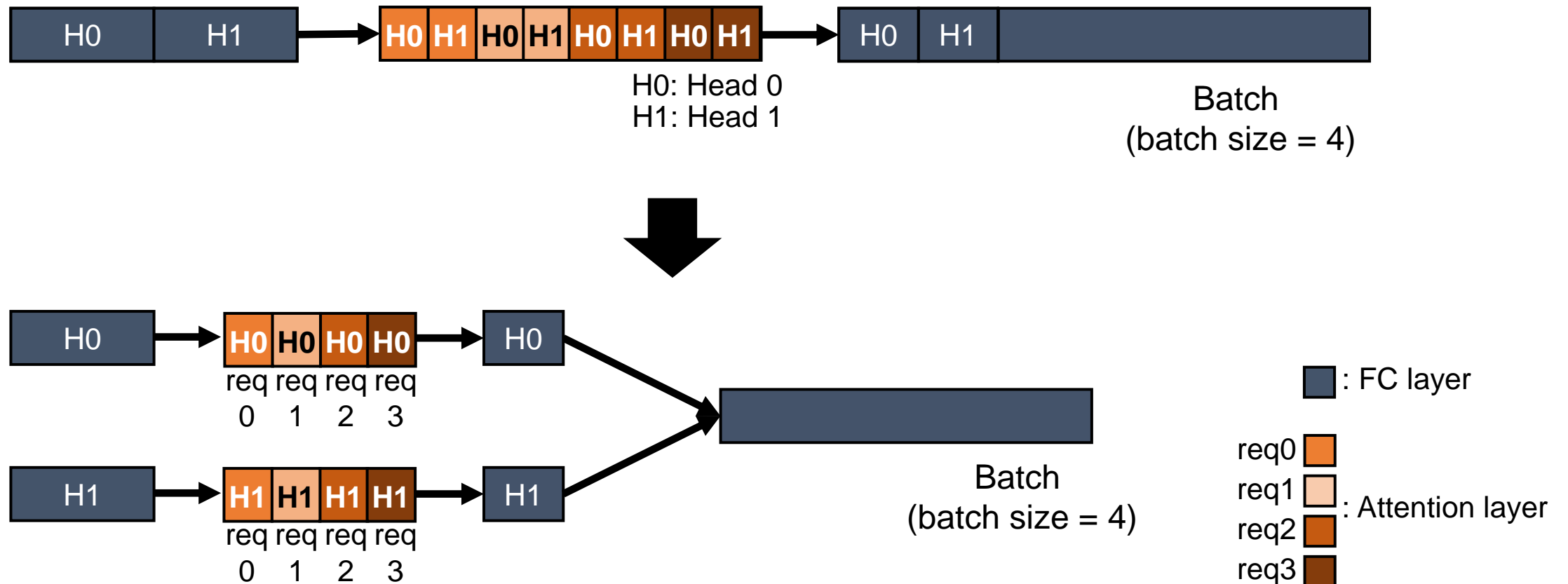


Naïve Approach: Batch-level Pipelining

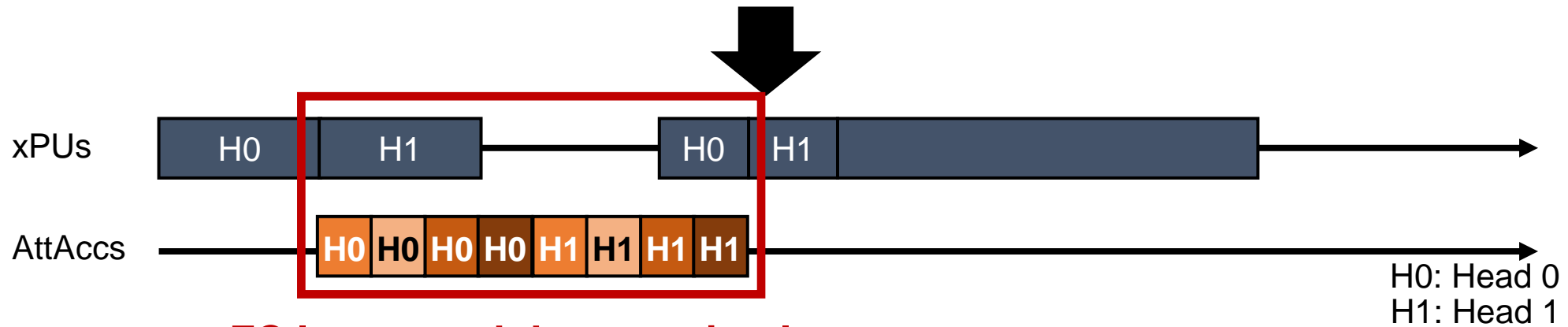
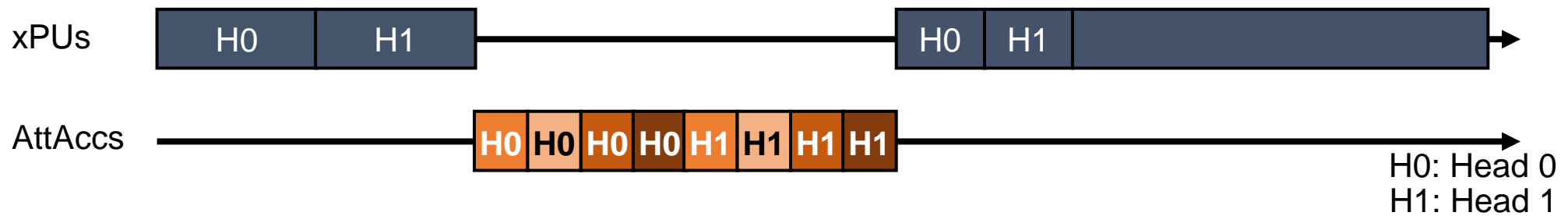


Head-level Pipelining

- FC layers that precede or follow the attention layer can be divided into heads.

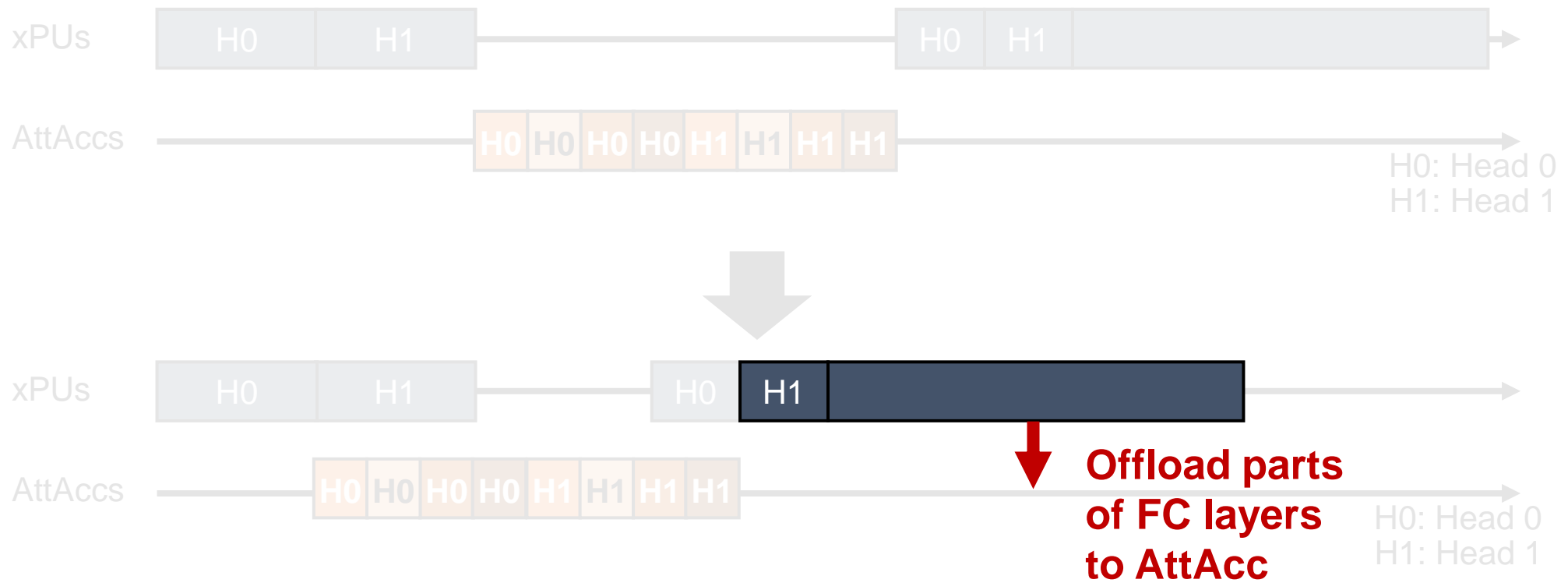


Head-level Pipelining

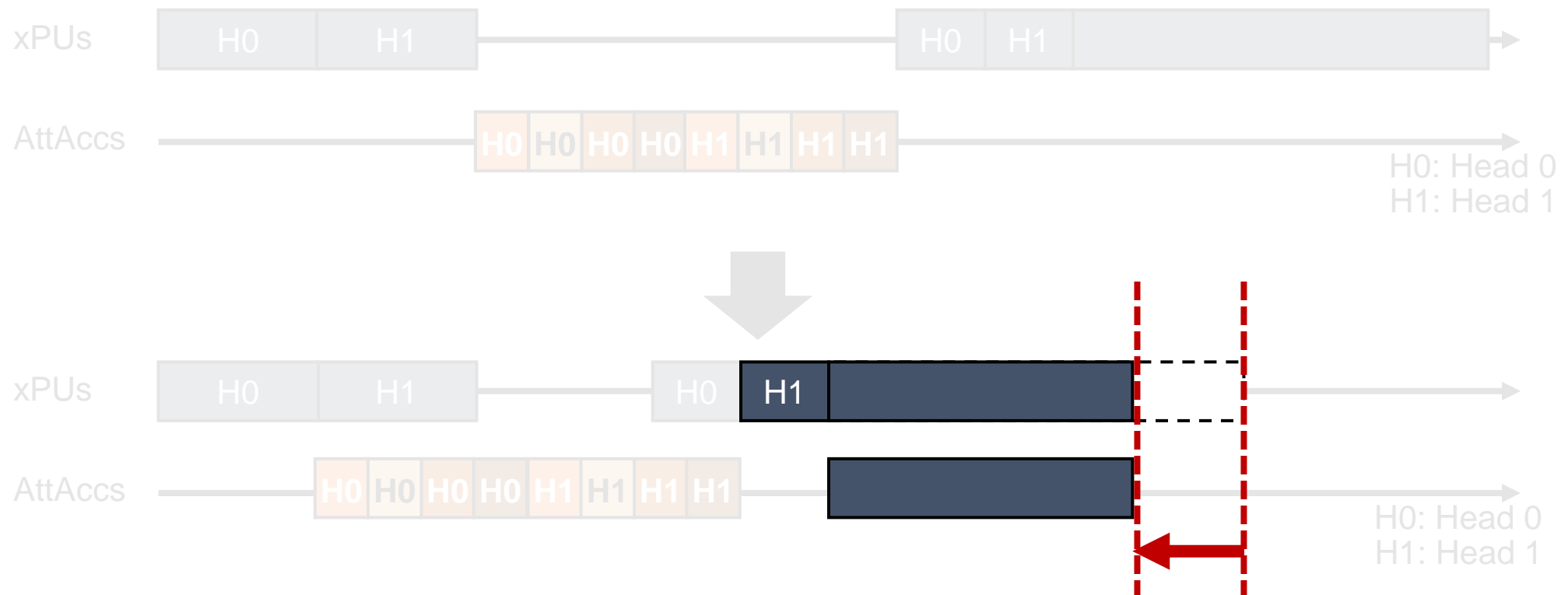


**FC layers and the attention layer
can be overlapped**

FeedForward Co-processing



FeedForward Co-processing

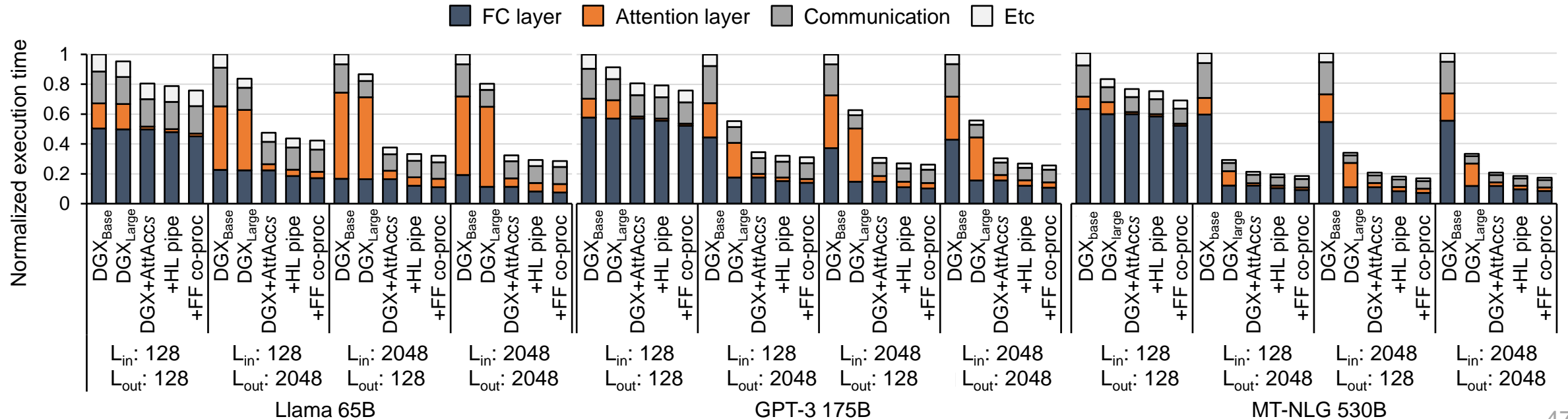


Experimental Setup

- Performance
 - Ramulator2 [1] and in-house simulator to evaluate **AttAcc** and DGX, respectively
- Energy and area
 - RTL synthesis for compute units and CACTI for buffer
 - The area overhead of **AttAccs** is 10.84% of a HBM.
 - = Scaling the area to DRAM process for units in DRAM die
- Target model
 - Various size of TbGMs: Llama 65B, GPT-3 175B, and MT-NLG 530B
- Comparison
 - DGX_{Base} : DGX-A100 having 40 HBM stacks
 - DGX_{Large} : DGX-A100 having 80 HBM stacks
 - $DGX+AttAcc$: $DGX_{Base} + 8$ **AttAccs** with 5 HBM stacks each

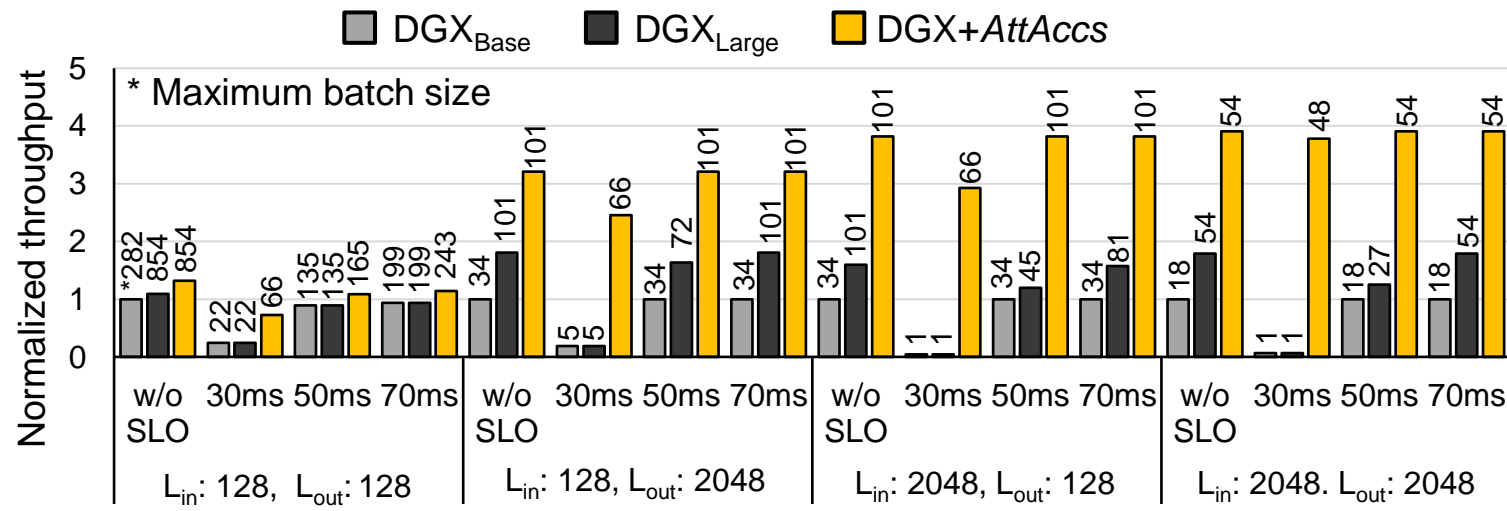
Evaluation (Performance)

- $DGX+AttAccs$ outperforms DGX_{Base} and even DGX_{Large} up to by 5.93x and 2.81x, respectively
 - 4.84x and 2.48x from **AttAcc**
 - 1.15x from head-level pipelining
 - 1.10x from feedforward co-processing



Evaluation (Performance)

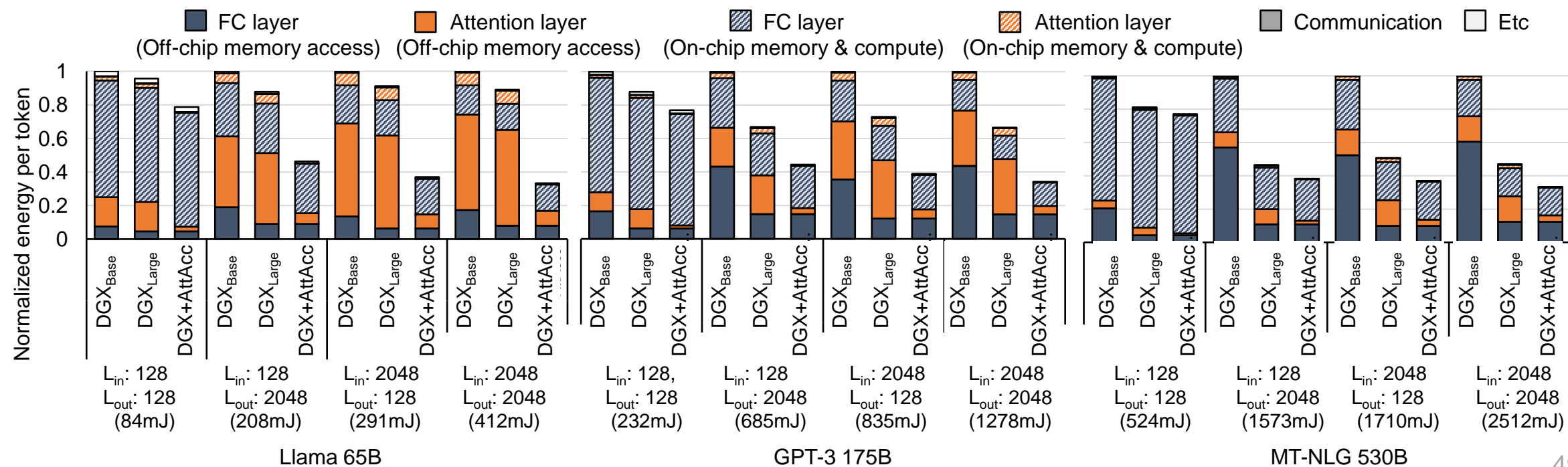
- *DGX+AttAccs* achieves further throughput improvement under SLO constraint
 - Performance improvement from relieving the batch size constraints caused by SLO



Normalized throughput of GPT-3 175B inference for various SLOs

Evaluation (Energy Efficiency)

- Energy consumption of $DGX+AttAccs$ compared to DGX_{Base} (DGX_{Large}) is reduced by up to
 - 66.7% (62.6%) for Llama 65B
 - 65.9% (48.8%) for GPT-3 175B
 - 66.8% (29.1%) for MT-NLG 530B



Conclusion

- We discovered that **the attention layer** poses a constraint on the batch size in conventional systems (e.g., DGX) due to the **long latency** and **memory capacity requirements**.
- We proposed a **heterogeneous system** (*DGX* + ***AttAccs***) with the conventional system for the batched FC layer and ***AttAccs*** for the attention layer, leveraging PIM architecture.
- We explored GEMV unit placement and data mapping in the PIM architecture and proposed efficient pipelining and co-processing optimizations to improve system utilization.
- *DGX+AttAccs* achieved higher throughput (up to 2.81×) and energy efficiency (up to 2.67×) compared to the monolithic GPU system.

Thank you!

Question?